AS3500 AS3501 AS3502

Data Sheet

Low Power Ambient Noise-Cancelling Speaker Driver

1 General Description

The AS3500/01/02 are speaker driver with Ambient Noise Cancelling function for handsets, headphones or ear pieces. It is intended to improve quality of e.g. music listening, a phone conversation etc. by reducing background ambient noise.

The fully analog implementation allows the lowest power consumption, lowest system BOM cost and most natural received voice enhancement otherwise difficult to achieve with DSP implementations. The device is designed to be easily applied to existing architectures.

An internal OTP-ROM can be optionally used to store the microphones gain calibration settings.

The AS3500/01/02 can be used in different configurations for best trade-off of noise cancellation, required filtering functions and mechanical designs.

The simpler feed-forward topology is used to effectively reduce low frequency background noise. The feed-back topology with either 1 or 2 filtering stages can be used to reduce noise for a larger frequency range, and to even implement transfer functions like speaker equalization, Baxandall equalization, high/low shelving filter and to set a predefined loop bandwidth.

The filter loop is optimized by the user for specific handset electrical and mechanical designs by dimensioning simple R, C components.

Most handset implementations will make use of a single noise detecting microphone. Two microphones could be used to allow for increased flexibility of their location in the handset mechanical design. Using the bridged mode allows to even drive high impedance headsets.

2 Key Features

Microphone Input

- 128 gain steps @0.375dB and MUTE with AGC
- differential, low noise microphone amplifier
- single ended or differential mode
- supply for electret microphone
- MIC gain OTP programmable

High Efficiency Headphone Amplifier

- 2x34mW, 0.1% THD @ 16Ω, 1.5V supply, 100dB SNR
- bridged mode for e.g. 300Ω loads
- click and pop less start-up and mode switching

Line Input

- volume control via serial interface or volume pin
- 64 steps @ 0.75dB and MUTE, pop-free gain setting
- single ended stereo or mono differential mode

ANC processing

- feed-forward cancellation
- feed-back cancellation with filter loop transfer function definable via simple RC components
- simple in production SW calibration
- 12-30dB noise reduction (headset dependent)
- 10-2000Hz wide frequency active noise attenuation (headset dependent)

Monitor Function

- for assisted hearing, i.e. to monitor announcements
- fixed (OTP prog.) ambient sound amplification to compensate headphone passive attenuation
- volume controlled ambient sound amplification mixed with fixed (OTP prog.) attenuation of LineIn

Incremental Functions

- ANC with or without music on the receiving path
- improved dynamic range playback
- simple and low cost single noise detection microphone implementation
- OTP ROM for automatic trimming during production

Performance Parameter

- 5/3.8mA @ 1.5V stereo/mono ANC; <1uA quiescent
- extended PSRR for 217Hz

Interfaces

- 2 wire serial control mode & volume inputs
- calibration via Line-In or 2-wire serial interface
- single cell or fixed 1.0-1.8V supply with internal CP

Package

- AS3500, AS3501 QFN24 [4x4mm] 0.5mm pitch
- AS3502 QFN32 [5.x5mm] 0.5mm pitch

3 Applications

Ear pieces, Headsets, Hands-Free Kits, Mobile Phones, Voice Communicating Devices

Figure 1. AS3501 Feed Forward ANC Block Diagram

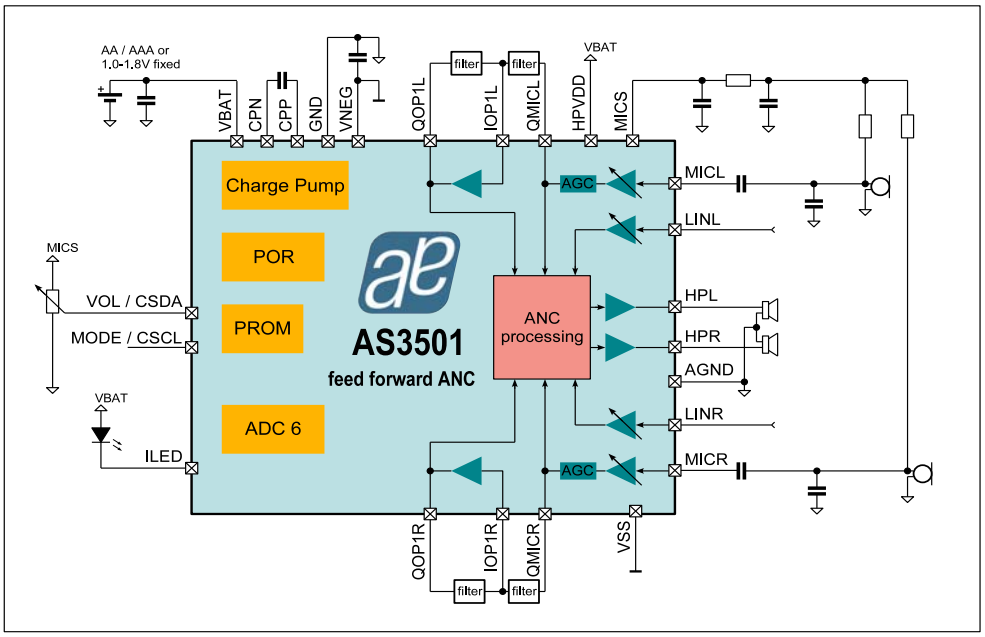


Figure 2. AS3502 Feed-Back Block Diagram

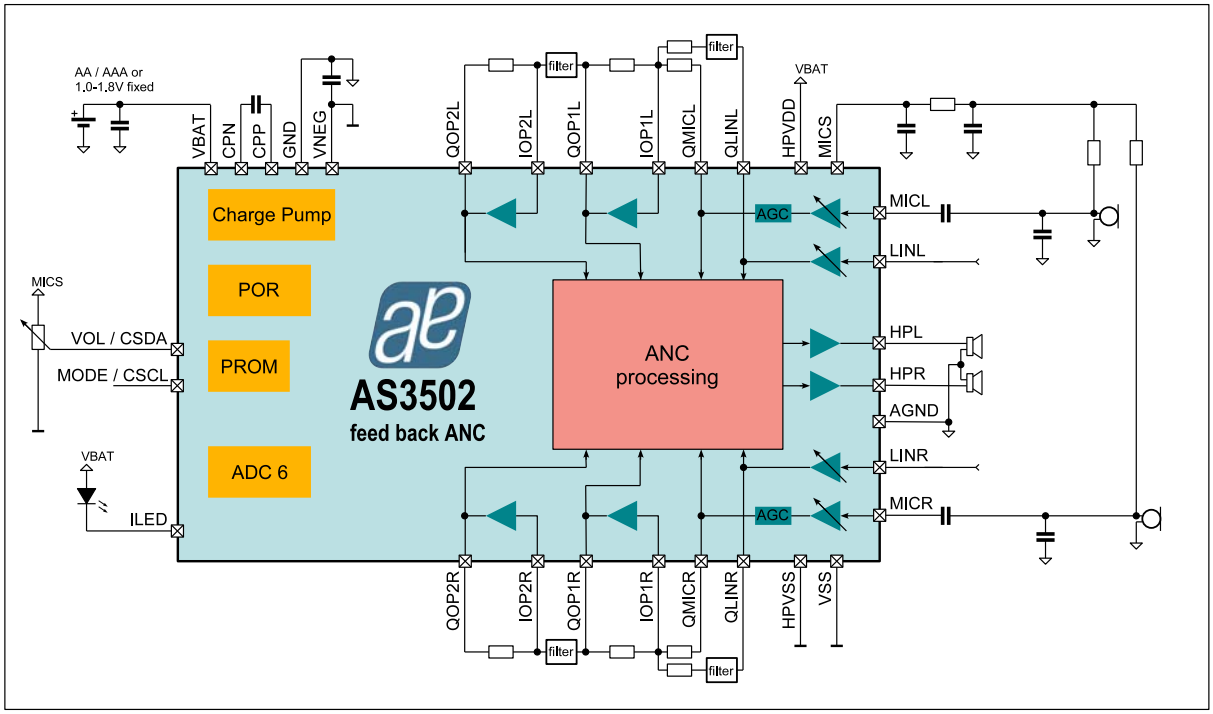
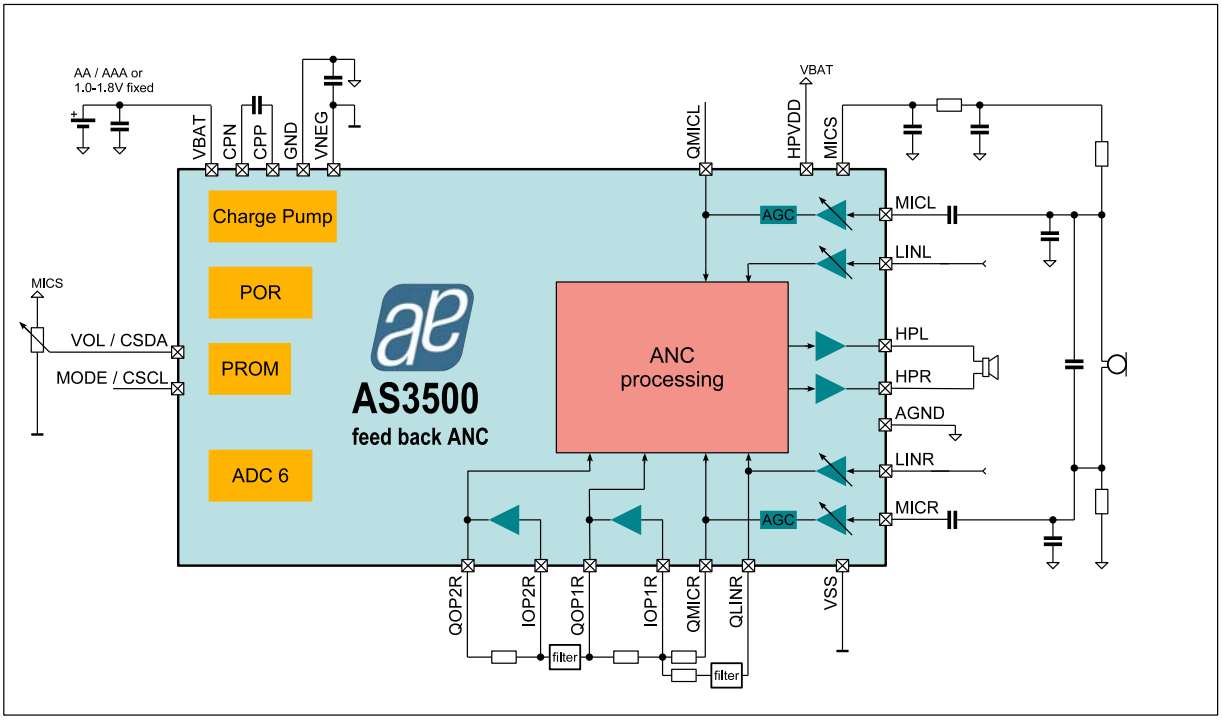


Figure 3. AS3500 Feed-Forward Block Diagram



Contents

Revision History

Table 1. Revision History

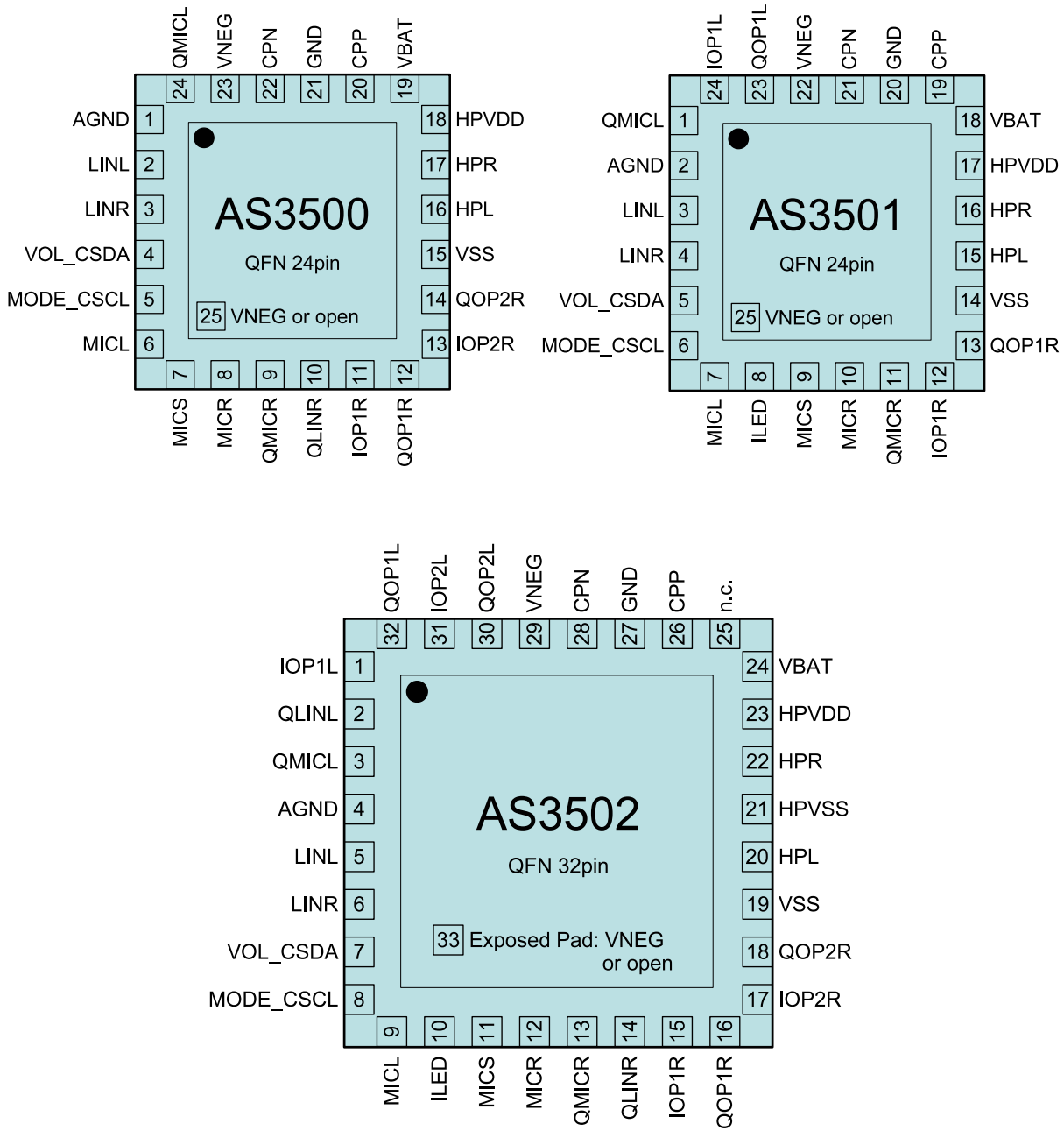
Revision	Date	Owner	Description
1.0	18.5.2009	pkm	official release
1.01	5.6.2009	pkm	updated application schematics
1.02	15.7.2009	pkm	typo correction
1.1	19.1.2009	pkm	updated pin and pinout description
1.11	03.8.2010	hgt	updated solder profile, power up sequences and block diagrams

4 Pinout

4.1 Pin Assignment

Please observe that pin assignment may change in preliminary data sheets.

Figure 4. Pin Assignments (Top View)



4.2 Pin Description

Please observe that pin description may change in preliminary data sheets.

Table 2. Pin Description for AS3500 AS3501 AS3502

AS3500	AS3501	AS3502	Pin Name	Type	Description
-	24	1	IOP1L	ANA IN	Filter OpAmp1 Input Left Channel
-	-	2	QLINL	ANA OUT	Line In GainStage Output Left Channel
24	1	3	QMICL	ANA OUT	MIC GainStage Output Right Channel
1	2	4	AGND	ANA IN	Analog Reference
2	3	5	LINL	ANA IN DIG IN	Line In Left Channel During Appl Trim Mode Write – CSDA During Appl Trim Mode Burn - VNEG
3	4	6	LINR	ANA IN DIG IO	LineIn Right Channel During Appl Trim Mode Write – CSCL During Appl Trim Mode Burn - Clock
4	5	7	VOL_CSDA	MIXED IO	Serial Interface Data ADC Input for volume regulation
5	6	8	MODE_CSCL	DIG IN	Mode Pin (PowerUp/Dn, Monitor) Serial Interface Clock
6	7	9	MICL	ANA IN	Microphone In Left Channel
-	8	10	ILED	ANA OUT	Current Output for on-indication LED
7	9	11	MICS	ANA OUT	Microphone Supply
8	10	12	MICR	ANA IN	Microphone Input Right Channel
9	11	13	QMICR	ANA OUT	MIC GainStage Output Right Channel
10	-	14	QLINR	ANA OUT	Line In GainStage Output Right Channel
11	12	15	IOP1R	ANA IN	FilterOpAmp1 Input Right Channel
12	13	16	QOP1R	ANA IN	Filter OpAmp1 Output Right Channel
13	-	17	IOP2R	ANA IN	Filter OpAmp2 Input Right Channel
14	-	18	QOP2R	ANA OUT	Filter OpAmp2 Output Right Channel
15	14	19	VSS	SUP IN	Core and Periphery Circuit VSS Supply
16	15	20	HPL	ANA OUT	Headphone Output Left Channel
-	-	21	HPVSS	SUP IN	Headphone VSS Supply
17	16	22	HPR	ANA OUT	Headphone Output Right Channel
18	17	23	HPVDD	SUP IN	Headphone VDD Supply
19	18	24	VBAT	SUP IN	VNEG ChargePump Positive Supply
-	-	25	n.c.	-	
20	19	26	CPP	ANA OUT	VNEG ChargePump Flying Capacitor Positive Terminal
21	20	27	GND	GND	VNEG ChargePump Negative Supply
22	21	28	CPN	ANA OUT	VNEG ChargePump Flying Capacitor Negative Terminal
23	22	29	VNEG	SUP IO	VNEG ChargePump Output
-	-	30	QOP2L	ANA OUT	Filter OpAmp2 Output Left Channel
-	-	31	IOP2L	ANA IN	Filter OpAmp2 Input Left Channel
-	23	32	QOP1L	ANA OUT	Filter OpAmp1 Output Right Channel
25	25	33			Exposed Pad: connect to VNEG or leave it unconnected

5 Absolute Maximum Ratings

Stresses beyond those listed in Table 3 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Electrical Characteristics on page 9 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. The device should be operated under recommended operating conditions.

Table 3. Absolute Maximum Ratings

Parameter	Min	Max	Units	Comments
Reference Ground				Defined as in GND
Supply terminals	-0.5	2.0	V	Applicable for pin VBAT, HPVDD
Ground terminals	-0.5	0.5	V	Applicable for pins AGND
Negative terminals	-2.0	0.5	V	Applicable for pins VNEG, VSS, HPVSS
Voltage difference at VSS terminals	-0.5	0.5	V	Applicable for pins VSS, HPVSS
Pins with protection to VBAT	VNEG -0.5	5.0 VBAT+0.5	V	Applicable for pins CPP, CPN
Pins with protection to HPVDD	VSS -0.5	5.0 HPVDD+0.5	V	Applicable for pins LINL/R, MICL/R, ILED, HPR, HPL, QMICL/R, QLINL/R, IOPx, QOPx
other pins	VSS -0.5	5		applicable for pins MICS, VOL_CSDA, MODE_CSCL
Input Current (latch-up immunity)	-100	100	mA	Norm: JEDEC 17
Continuous Power Dissipation (T_A = +70ºC)				
Continuous Power Dissipation	-	200	mW	P_T[1] for QFN16/24/32 package
Electrostatic Discharge				
Electrostatic Discharge HBM		+/-2	kV	Norm: JEDEC JESD22-A114C
Temperature Ranges and Storage Conditions				
Operating Temperature Range	-20	+85	ºC	
Junction Temperature		+110	ºC	
Storage Temperature Range	-55	+125	ºC	
Humidity non-condensing	5	85	%	
Bump Temperature (soldering)				
Package Body Temperature		260	°C	Norm IPC/JEDEC J-STD-020C

1. Depending on actual PCB layout and PCB used

6 Electrical Characteristics

VBAT = 1.0V to 1.8V, T_A = -20ºC to +85ºC. Typical values are at VBAT = 1.5V, T_A = +25ºC, unless otherwise specified.

Table 4. Electrical Characteristics

Symbol	Parameter	Condition	Min	Max	Unit
Supply Voltages					
GND	Reference Ground		0	0	V
VBAT, HPVDD	Battery Supply Voltage	normal operation MODE pin high	1.0	1.8	V
		two wire interface operation	1.4	1.8	V
VNEG	ChargePump Voltage		-1.8	-0.7	V
VSS	Analog neg. Supply Voltages HPVSS, VSS, VNEG		-1.8	-0.7	V
V_{DELTA-}	Difference of Ground Supplies GND, AGND	To achieve good performance, the negative supply terminals should be connected to low impedance ground plane.	-0.1	0.1	V
$V_{DELTA--}$	Difference of Negative Supplies VSS, VNEG, HPVSS	Charge pump output or external supply	-0.1	0.1	V
V_{DELTA+}	Difference of Positive Supplies	VBAT-HPVDD	-0.25	0.25	V
other pins					
V_{MICS}	Microphone Supply Voltage	MICS	0	3.6	V
V_{HPVDD}	pins with diode to HPVDD	MICL/R, ILED, HPR, HPL, QMICL/R, QLINL/R, IOPx, QOPx	VSS	3.6	V
V_{VBAT}	pins with diode to VBAT	CPP, CPN	VNEG	VBAT	V
$V_{CONTROL}$	Control Pins	MODE_CSCL, VOL_CSDA	VSS	3.7	V
V_{TRIM}	Line Input & Application Trim Pins	LINL, LINR	VNEG -0.5 or -1.8	HPVDD +0.5 or 1.8	V

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Block Power Requirements @ 1.5V VBAT						
I_{SYS}	Reference supply current	bias generation, oscillator, ILED current sink, ADC6		0.25		mA
I_{LIN}	LineIn gain stage current	no signal, stereo		0.64		mA
I_{MIC}	Mic gain stage current	no signal, stereo		2.10		mA
I_{HP}	Headphone stage current	no signal		1.70		mA
I_{VNEG}	VNEG charge pump current	no load		0.25		mA
I_{MICS}	MICS charge pump current	no load		0.06		mA
I_{MIN}	minimal supply current	sum of all above blocks		5.00		mA
I_{OP1}	OP1 supply current	no load		0.64		mA
I_{OP2}	OP2 supply current	no load		0.64		mA
I_{ILED}	ILED current sink current	100% duty cycle		2.50		mA
I_{MICB}	Microphone bias current	200uA per microphone via charge pump		1.30		mA

7 Typical Operating Characteristics

VBAT = +1.5V, T_A = +25ºC, unless otherwise specified.

Figure 5. LIN to HPH: THD+N versus Output Power

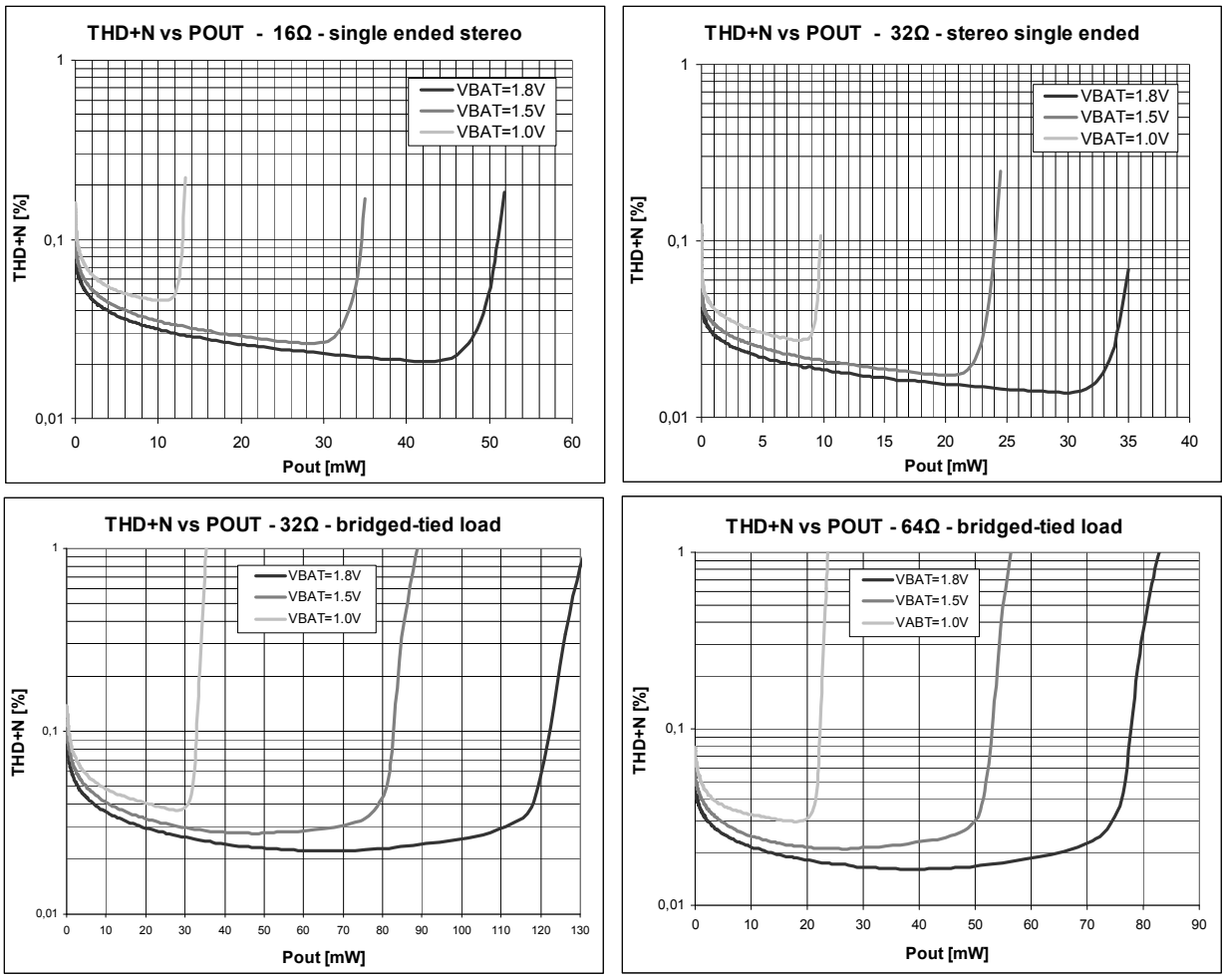


Figure 6. VNEG Charge Pump

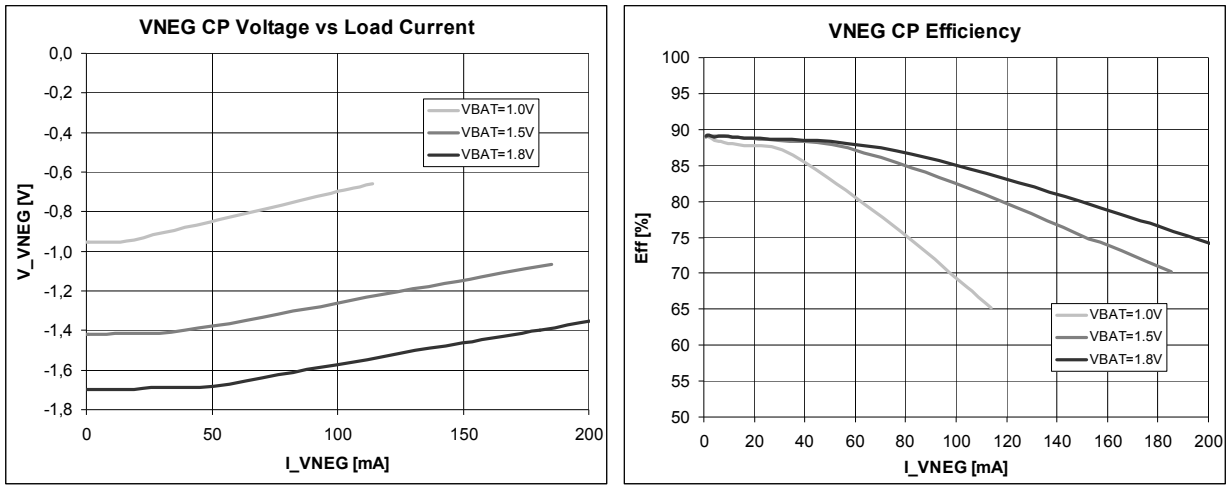


Figure 7. Microphone Supply Generation

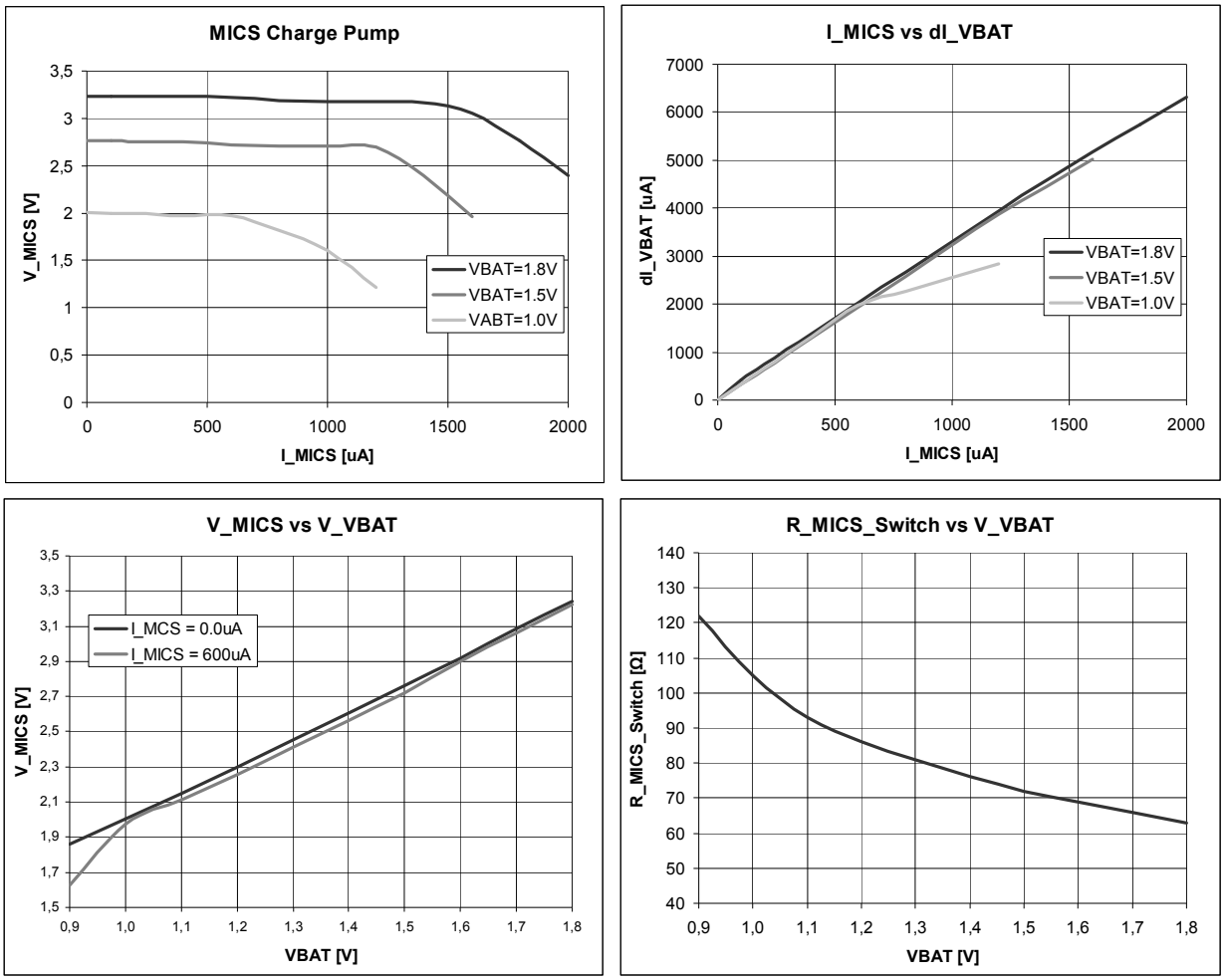


Figure 8. ILED Current Sink (100% PWM setting)

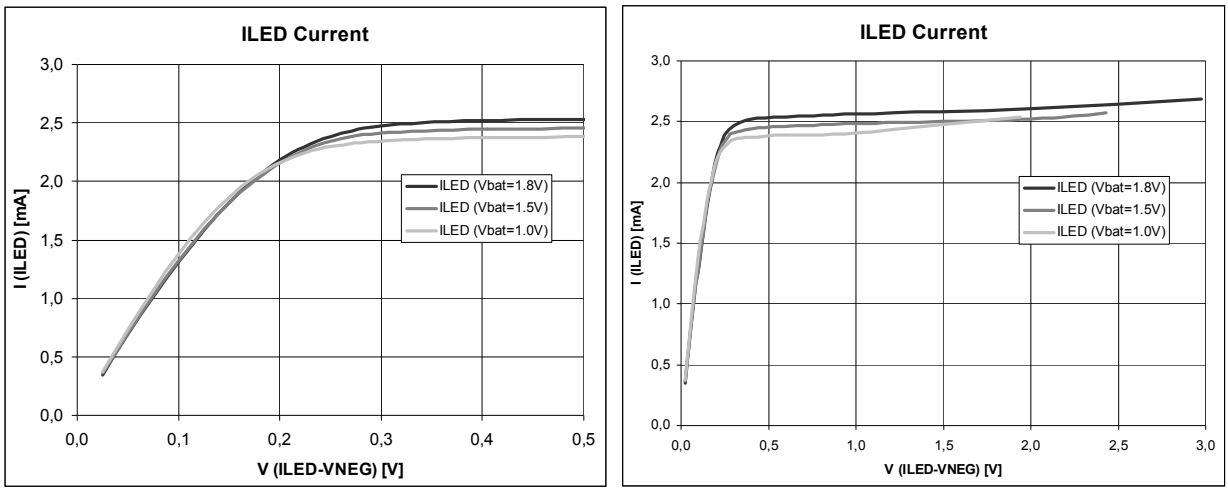
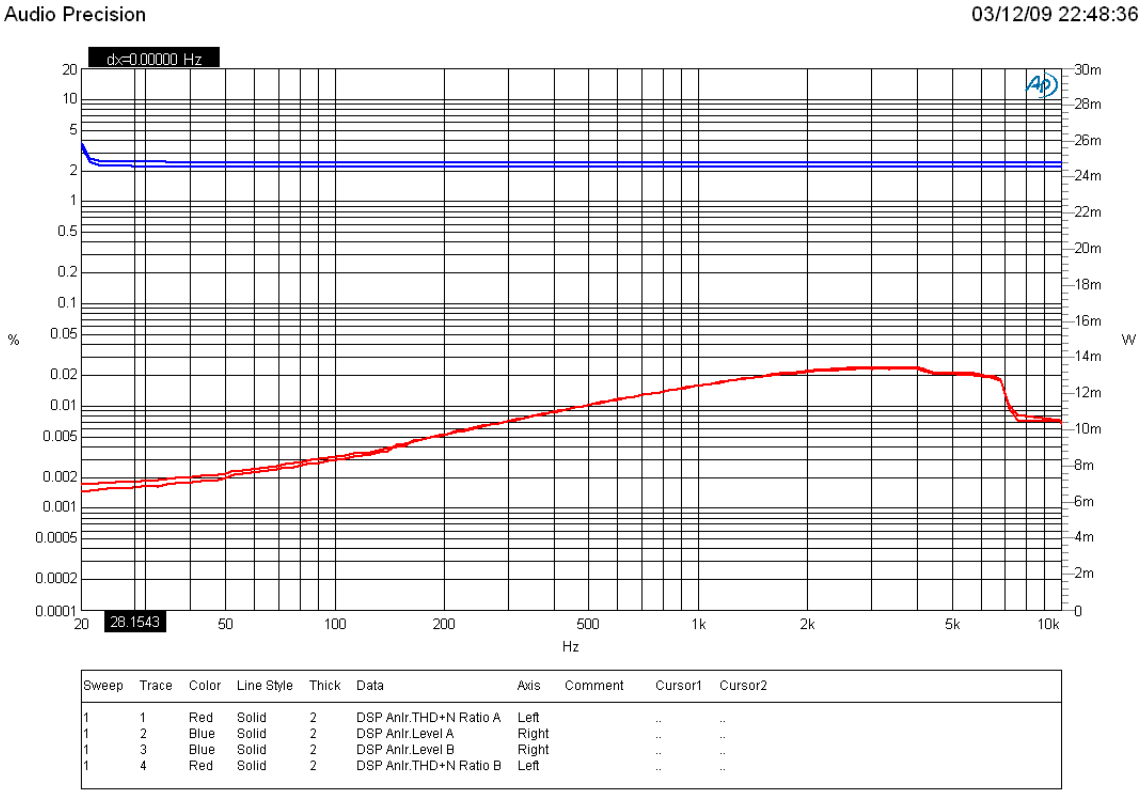
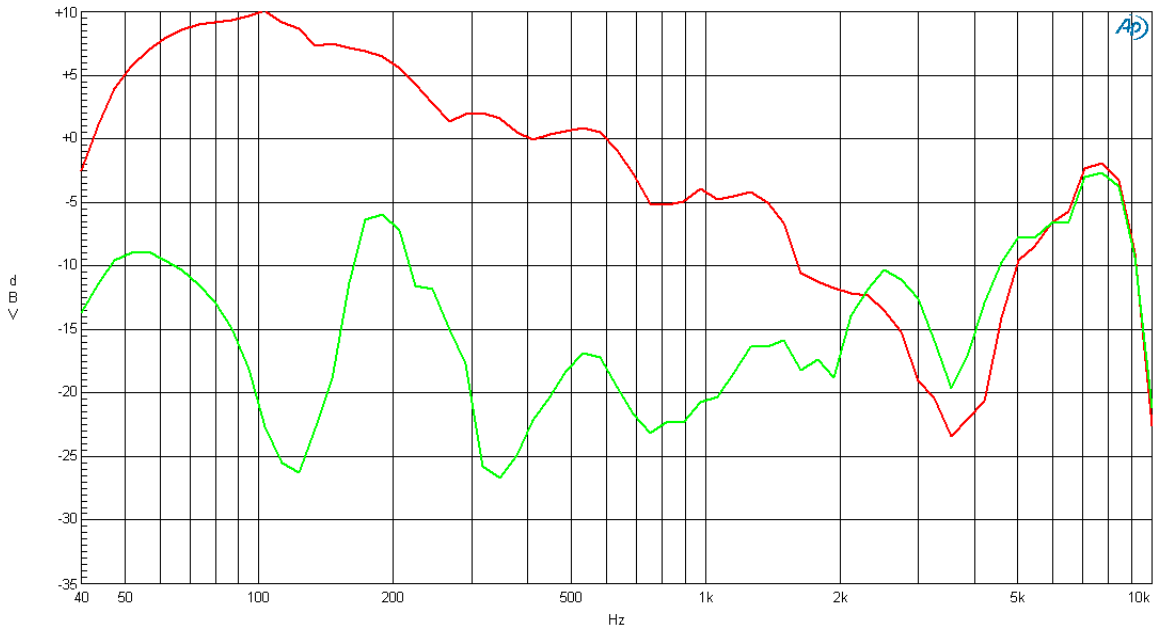


Figure 9. THD vs. frequency @ 1.5V, 16Ω, 25mW



Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment	Cursor1	Cursor2
1	1	Red	Solid	2	DSP Anlr.THD+N Ratio A	Left		..	..
1	2	Blue	Solid	2	DSP Anlr.Level A	Right		..	..
1	3	Blue	Solid	2	DSP Anlr.Level B	Right		..	..
1	4	Red	Solid	2	DSP Anlr.THD+N Ratio B	Left		..	..

Figure 10. Typical Performance Data, FF configuration



Sweep	Trace	Color	Line Style	Thick	Data	Axis	Comment
5	1	Red	Solid	2	DSP Anlr.Bandpass BlSmooth	Left	AMS PassiveL
7	1	Green	Solid	2	DSP Anlr.Bandpass BlSmooth	Left	AMS Active 1001 L

8 Detailed Description

8.1 Audio Line Input

8.1.1 General

The chip features one line input. The blocks can work in mono differential or in stereo single ended mode.

In addition to the 12.5-25kΩ input impedance, LineIn has a termination resistor of 10kΩ which is also effective during MUTE to charge eventually given input capacitors.

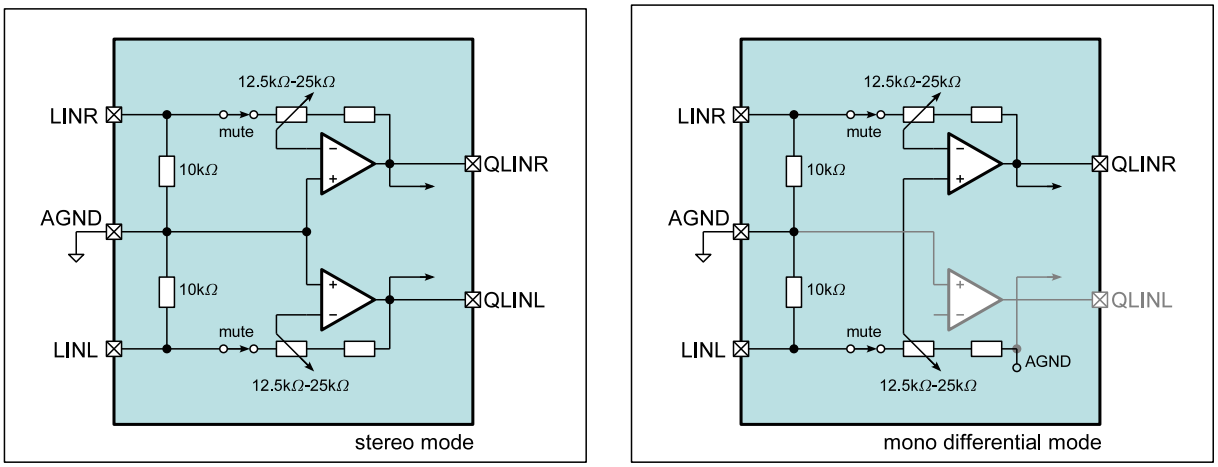
8.1.2 Gain Stage

The Line In gain stage is designed to have 63 gain steps of 0.75dB with a max gain of 0dB plus MUTE.

In default, the gain will be ramped up from MUTE to 0dB during startup. There is a possibility to make the playback volume user controlled by the VOL pin with an ADC converted VOL voltage or UP/DN buttons.

In monitor mode the gain stage can be set to an fixed default attenuation level for reducing the loudness of the music.

Figure 11. Line Inputs



8.1.3 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 5. Line Input Parameter

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V_{LIN}	Input Signal Level			0.6* VBAT	VBAT	V_{PEAK}
R_{LIN}	Input Impedance	0dB gain (12.5k // 10k)		5.6		kΩ
		-46.5dB gain (25k // 10k)		7.2		kΩ
		MUTE		10		kΩ
Δ_{RLIN}	Input Impedance Tolerance			±30		%
C_{LIN}	Input Capacitance			5		pF
A_{LIN}	Programmable Gain		-46.5		+0	dB
	Gain Steps	discrete logarithmic gain steps		0.75		dB
	Gain Step Accuracy			0.5		dB
$A_{LINMUTE}$	Mute Attenuation			100		dB

Table 5. Line Input Parameter (Continued)

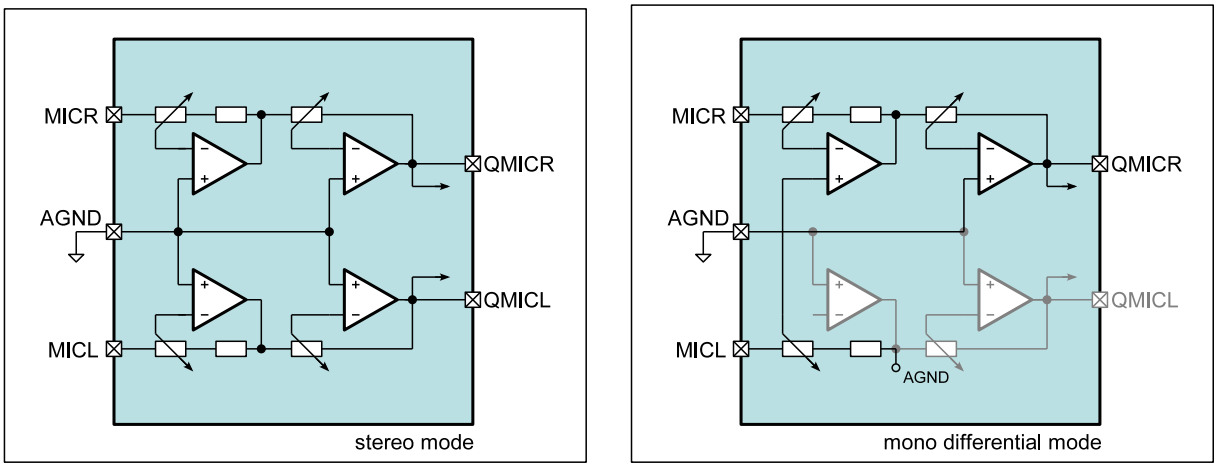
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Δ_{ALIN}	Gain Ramp Rate	PotiMode, Tinit=100ms		20		ms/ step
		ButtonMode, Tinit=400ms		80		
		MonitorMode		8		
V_{ATTACK}	Limiter Activation Level	HPL/R start of neg. clipping				V_{PEAK}
V_{DECAY}	Limiter Release Level	HPL/R		VNEG +0.3		V_{PEAK}
t_{ATTACK}	Limiter Attack Time			4		µs
t_{DECAY}	Limiter Decay Time			8		ms

8.2 Microphone Input

8.2.1 General

The AFE offers two microphone inputs and one low noise microphone voltage supply (microphone bias). The inputs can be switched to single ended or differential mode.

Figure 12. Microphone Input



8.2.2 Gain Stage & Limiter

The Mic GainStage has programmable Gain within -6dB…+41.625dB in 128 steps of 0.375dB.

As soft-start function is implemented for an automatic gain ramping implemented with steps of 4ms to fade in the audio at the end of the start-up sequence.

A limiter automatically attenuates high input signals. The AGC has 127 steps with 0.375dB with a dynamic range of the full gain stage.

In monitor mode the gain stage can be set to an fixed (normally higher) gain level or be controlled by the VOL pin.

8.2.3 Supply

The MICS charge pump is providing a proper microphone supply voltage for the AAA supply. Since AAA batteries are operating down to 1.0V, the direct battery voltage cannot be used for mic-supply. There are 2 modes.

The first mode SWITCH-MODE for 1.8V supply is to have just a switch from VBAT to MICS. With this switch, the microphone current is switched off in idle mode.

The second mode CHAREGPUMP_MODE for AAA batteries is the real charge pump mode, in this mode a positive voltage is generated of about 2* VBAT.

It is also possible to switch off the microphone supply if not needed (e.g. playback without ANC)

8.2.4 Parameter

VBAT=1.5V, T_A= 25°C unless otherwise mentioned

Table 6. Microphone Input Parameter

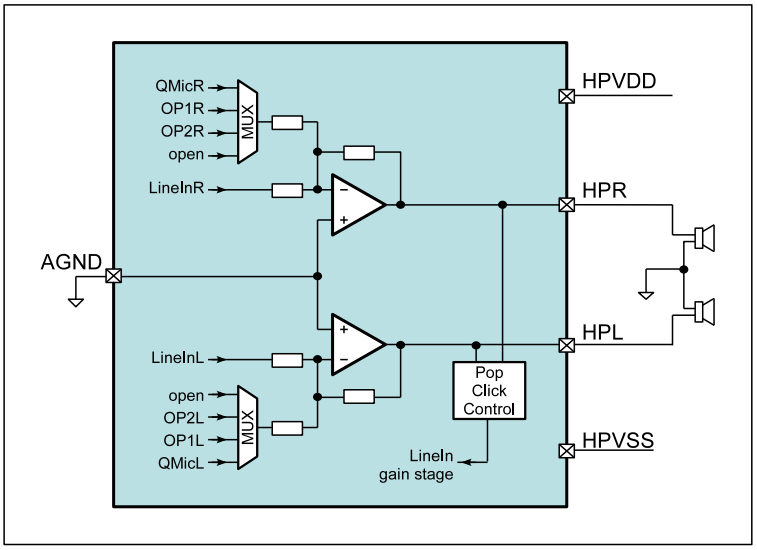
Symbol	Parameter	Condition	Min	Typ	Max	Unit
$V_{MICIN}0$	Input Signal Level	A_{MIC} = 30dB		20		mV_P
$V_{MICIN}1$		A_{MIC} = 36dB		10		mV_P
$V_{MICIN}2$		A_{MIC} = 42dB		5		mV_P
R_{MICIN}	Input Impedance	MICP to AGND		7.5		kΩ
Δ_{MICIN}	Input Impedance Tolerance			-7 +33		%
C_{MICIN}	Input Capacitance			5		pF
A_{MIC}	Programmable Gain		-6		+41.6	dB
	Gain Steps	discrete logarithmic gain steps		0.375		dB
	Gain Step Precision			0.15		dB
Δ_{AMIC}	Gain Ramp Rate	Tinit=64ms		4		ms/ step
V_{ATTACK}	Limiter Activation Level	V_{PEAK} related to VBAT or VNEG		0.67		1
V_{DECAY}	Limiter Release Level			0.4		1
$A_{MICLIMIT}$	Limiter Gain Overdrive	127 @ 0.375dB		41.625		dB
t_{ATTACK}	Limiter Attack Time			5		µs/ step
$t_{DECAY-DEB}$	Limiter Decay Debouncing Time			64		ms
t_{DECAY}	Limiter Decay Time			4		ms/ step
V_{MICS}	Microphone Supply Voltage			VBAT*2-240mV		V
$I_{MICSMIN}$	Min. Microphone Supply Current	VBAT=+1.0V VNEG=-0.7V MICS=+1.75V		650		uA
R_{OUT_CP}	CP Output Resistance			1300		Ω

8.3 Headphone Output

8.3.1 General

The headphone output is a true ground output using VNEG as negative supply, designed to provide the audio signal with 2x12mW @ 16Ω–64Ω, which are typical values for headphones. It is also capable to operate in bridged mode for higher impedance (e.g. 300Ω) headphone. In this mode the left output is carrying the inverted signal of the right output.

Figure 13. Headphone Output



8.3.2 Input Multiplexer

The signal from the line-input gain stage gets summed at the input of the headphone stage with the microphone gain stage output, the first filter opamp output or the second filter opamp output. The microphone gain stage output is used per default. It is also possible to playback without ANC by only using the line-input gain stage with no other signal on the multiplexer.

For the monitor mode the setting of this input multiplexer can be changed to an other source, normally to the microphone.

8.3.3 No-Pop Function

The No-Pop startup of the headphone stage takes 60ms to 120ms dependent on the supply voltage.

8.3.4 No-Clip Function

The headphone output stage gets monitored by comparator stages which detect if the output signal starts to clip.

This signal is used to reduce the LineIn gain to avoid distortion of the output signal. A hystereses avoids jumping between 2 gain steps for a signal with constant amplitude.

8.3.5 Over-current protection

The over-current protection has a threshold of 150-200mA and a debouncing time of 8us. The stage is forced to OFF mode in an over-current situation. After this the headphone stage tries to power up again every 8ms as long as the over-current situation still exists or the stage is turned off manually.

8.3.6 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 7. Headphone Output Parameter

Symbol	Parameter	Condition	Min	Typ	Max	Unit
R_{L_HP}	Load Impedance	stereo mode	16			Ω
C_{L_HP}	Load Capacitance	stereo mode			100	pF
P_{HP}	Nominal Output Power	RL=16Ω-64Ω	12			mW
P_{SRRHP}	Power Supply Rejection Ratio	200Hz-20kHz, 720mVpp, RL=16Ω		90		dB

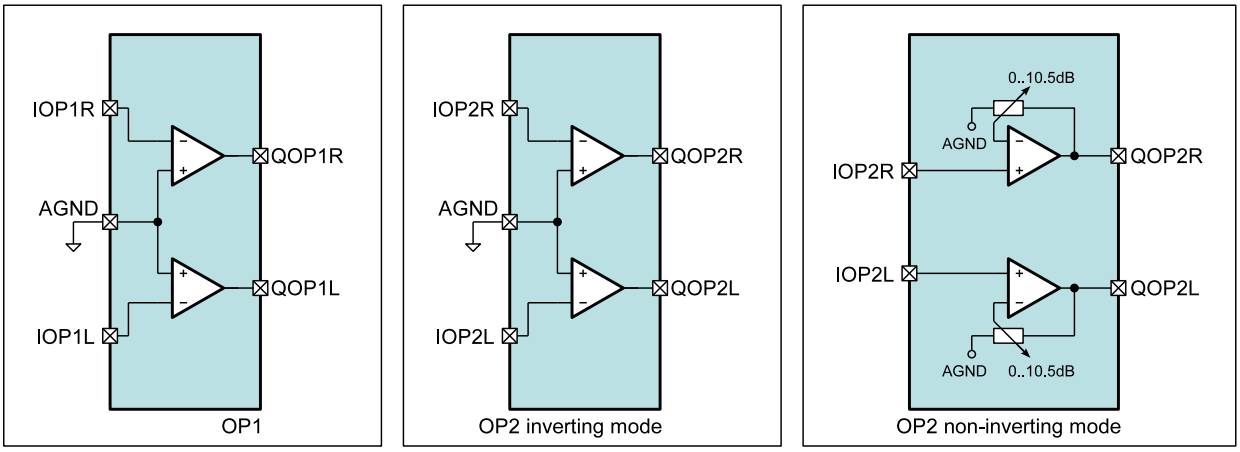
8.4 Operational Amplifier

8.4.1 General

While AS3501 offers only one operational amplifiers for feed-forward ANC, AS3500 and AS3502 feature an additional second operational amplifier stage to perform feed-back ANC or any other additional needed filtering.

Both operational amplifiers stages can be activated and used individually. While OP1 stage is always configured as inverting amplifier OP2 stage can be also switched to a non-inverting mode with an adjustable gain of 0..+10.5dB.

Figure 14. Operational Amplifiers



8.4.2 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 8. Headphone Output Parameter

Symbol	Parameter	Condition	Min	Typ	Max	Unit
R_{L_OP}	Load Impedance	single ended	1			kΩ
C_{L_OP}	Load Capacitance	single ended			100	pF
GBW_{OP}	Gain Band Width			4.3		MHz
V_{OS_OP}	Offset Voltage				6	mV
V_{EIN_HP}	Equivalent Input Noise	200Hz-20kHz		2.6		uV

8.5 SYSTEM

8.5.1 General

The system block handles the power up and power down sequencing. As well as the mode switching.

8.5.2 Power Up/Down Conditions

The chip powers up when one of the following condition is true:

Table 9. Power UP Conditions

#	Source	Description
1	MODE pin	In stand-alone mode, MODE pin has to be driven high to turn on the device
2	I2C start	In I2C mode, a I2C start condition turns on the device

The chip automatically shuts off if one of the following conditions arises:

Table 10. Power DOWN Conditions

#	Source	Description
1	MODE pin	Power down by driving MODE pin to low
2	SERIF	Power down by SERIF writing 0h to register 20h bit <0>
3	Low Battery	Power down if VBAT is lower than the supervisor off-threshold
4	VNEG CP OVC	Power down if VNEG is higher than the VNEG off-threshold

8.5.3 Start-up Sequence

The start-up sequence depends on the used mode.

In stand-alone mode the sequence runs automatically, in I2C mode the sequence runs till a defined state and waits then for an I2C command. Either the automatic sequence is started by setting the CONT_PWRUP bit in addition to the PWR_HOLD bit. If only the PWR_HOLD is set all enable bits for headphone, microphone, etc have to be set manually.

Figure 15. Stand-Alone Mode Start-Up Sequence

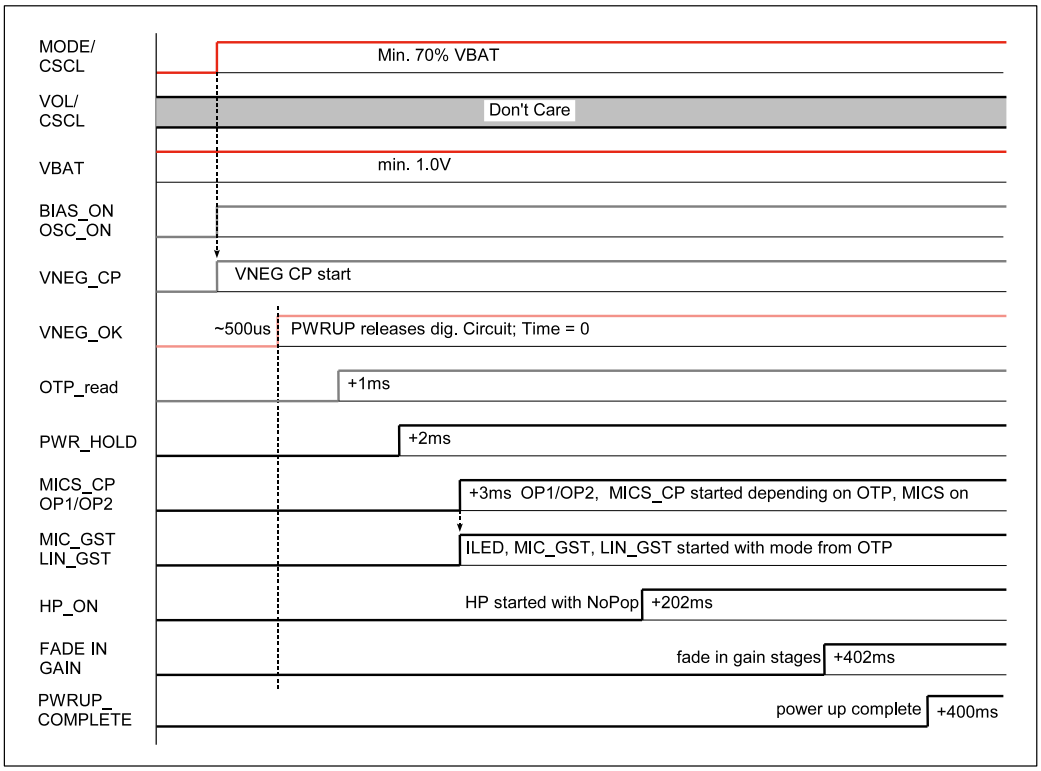
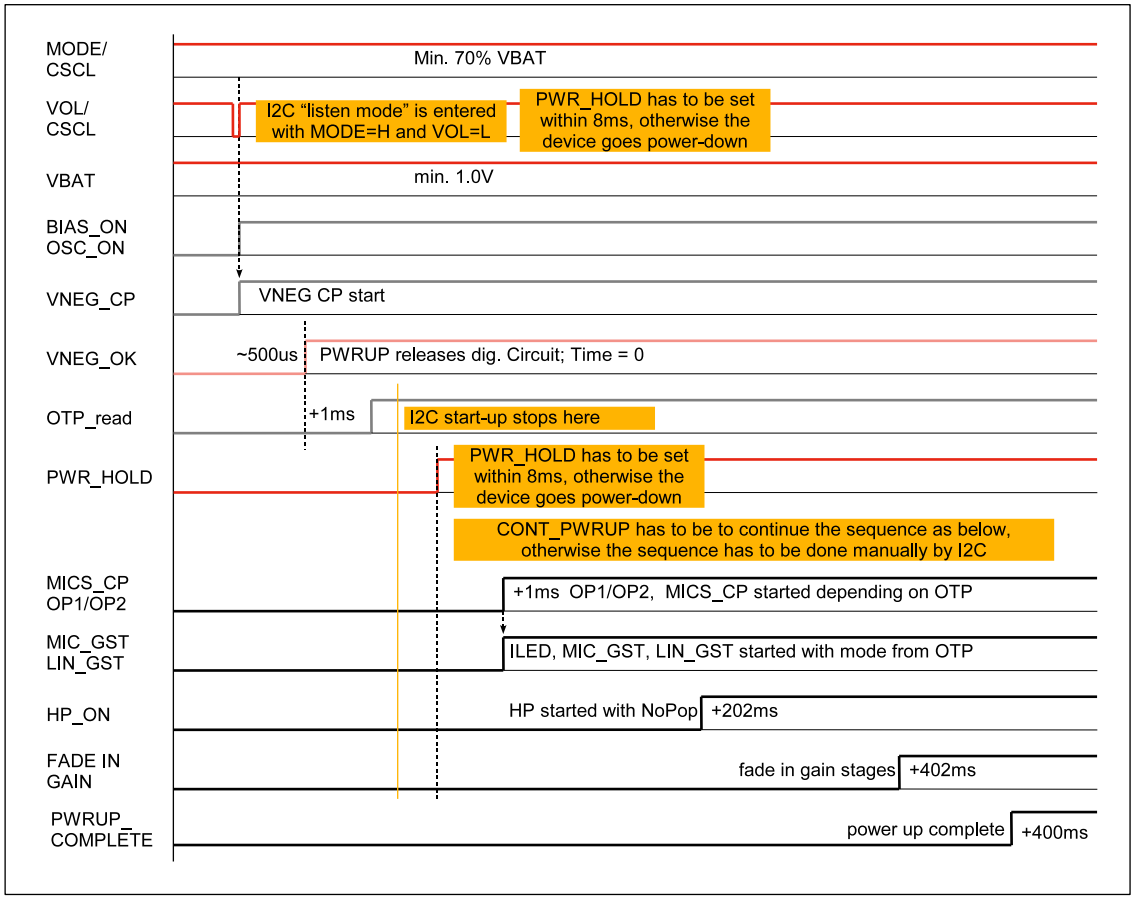


Figure 16. I2C Mode Start-Up Sequence



8.5.4 Mode Switching

When the chip in stand-alone mode (no I2C control) the mode can be switched with different levels on the MODE pin.

Table 11. Operation Modes

MODE	MODE pin	Description
OFF	LOW (VNEG)	Chip is turned off
ANC	HIGH (VBAT)	Chip is turned on and active noise cancellation is active
MONITOR	TRI-STATE (VBAT/2)	Chip is turned on and monitor mode is active In Monitor mode a different (normally higher) microphone preamplifier gain can be chosen to get an amplification of the surrounding noise. This volume can be either fixed or be controlled by the VOL input. To get rid of the low pass filtering needed for the noise cancellation, the headphone input multiplexer can be set to a different (normally to MIC) source. In addition the LineIn gain can be lowered to reduce the loudness of the music currently played back.

In I2C mode the monitor mode can be activated be setting the corresponding bit in the system register.

8.5.5 Status Indication

AS3501and AS3502 features a on-status information via the current output pin ILED. The current can be controlled in 3 steps and be switched off, by setting the PWM accordingly (0%, 25%, 50% and 100% duty cycle of a 50kHz PWM signal).

If LOW_BAT is active, ILED switches to blinking with 1Hz, 50% duty cycle and 50% current setting.

8.6 VNEG Charge Pump

8.6.1 General

The VNEG charge pump uses one external 1uF capacitor to generate a negative supply voltage out of the battery input voltage to supply all audio related blocks. This allows a true-ground headphone output with no more need of external dc-decoupling capacitors.

8.6.2 Parameter

VBAT=1.5V, T_A= 25°C, unless otherwise mentioned

Table 12. Headphone Output Parameter

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V_{IN}	input voltage	VBAT	1.0	1.5	1.8	V
V_{OUT}	output voltage	VNEG	-0.7	-1.5	-1.8	V
C_{EXT}	external flying capacitor			1		uF

8.7 OTP Memory & Internal Registers

8.7.1 General

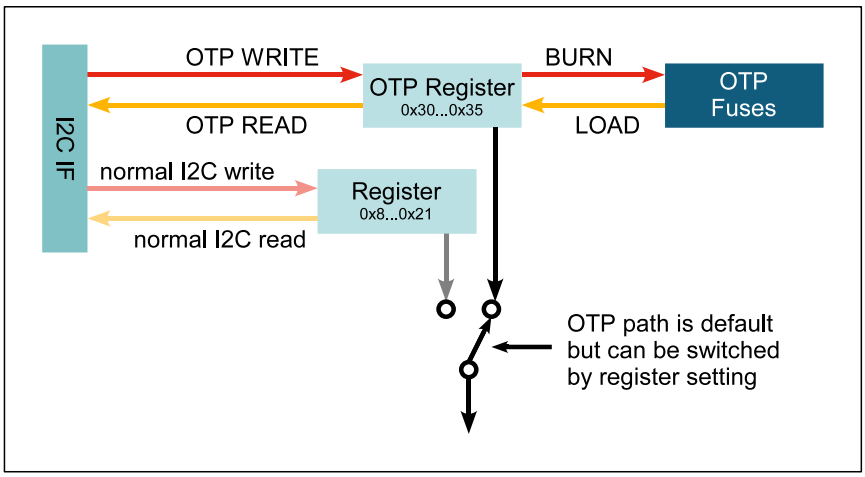
The OTP memory consists of OTP register and the OTP fuses.The OTP register can be written as often as wanted but will lose the content on power off. The OTP fuses are intended to store basic chip configurations as well as the micro-phone gain settings to optimize the ANC performance and get rid of sensitivity variations of different microphones. Burning the fuses can only be once and is a permanent change, which means the fuses keep the content even if the chip is powered down.

When the chip is controlled by a microcontroller via I2C, the OTP memory don't has to be used.

8.7.2 Register & OTP Memory configuration

The following graphics is showing the principal register interaction.

Figure 17. Register Access



Registers 0x8, 0x9, 0xA, 0xB, 0xC and 0x21 have only effect when the corresponding "REG_ON" bit is set, otherwise the chip operates with the OTP Register settings which are loaded from the OTP fuses at every start-up.

All registers settings can be changed several times, but will loose the content on power off. When using the I2C mode the chip configuration has to be loaded from the microcontroller after every start-up. In stand alone mode the OTP fuses have to be programmed for a permanent change of the chip configuration.

A single OTP cell can be programmed only once. Per default, the cell is “0”; a programmed cell will contain a “1”. While it is not possible to reset a programmed bit from “1” to “0”, multiple OTP writes are possible, but only additional unprogrammed “0”-bits can be programmed to “1”.

Independent of the OTP programming, it is possible to overwrite the OTP register temporarily with an OTP write command at any time. This setting will be cleared and overwritten with the hard programmed OTP settings at each power-up sequence or by a LOAD operation.

The OTP memory can be accessed in the following ways:

LOAD Operation:

The LOAD operation reads the OTP fuses and loads the contents into the OTP register. A LOAD operation is automatically executed after each power-on-reset.

WRITE Operation:

The WRITE operation allows a temporary modification of the OTP register. It does not program the OTP. This operation can be invoked multiple times and will remain set while the chip is supplied with power and while the OTP register is not modified with another WRITE or LOAD operation.

READ Operation:

The READ operation reads the contents of the OTP register, for example to verify a WRITE command or to read the OTP memory after a LOAD command.

BURN Operation:

The BURN operation programs the contents of the OTP register permanently into the OTP fuses. Don’t use old or nearly empty batteries for burning the fuses.

Attention: If you once burn the OTP_LOCK bit no further programming, e.g. setting additional “0” to “1”, of the OTP can be done.

For production the OTP_LOCK bit must be set to avoid an unwanted change of the OTP content during the livetime of the product.

8.7.3 OTP fuse burning

In most stand alone applications the I2C pins are not accessible. Burning the fuses can be done by switching the line inputs into a special mode to access the chip by I2C over the line input connections. This allows trimming of the microphone gain with no openings in the final housing and so no influence to the acoustic of the headset.

This mode is called “Application Trimm” mode, or short “APT”. (Patent Pending)

During the application trimm mode LINR has to provide the clock, while LINL has to provide the data for the I2C communication.

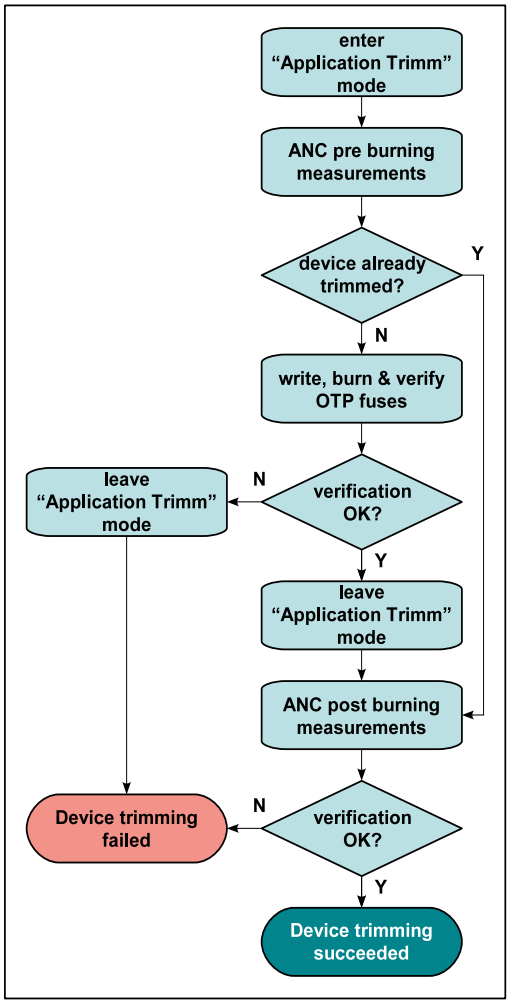
Please note that the OTP register cannot be accessed directly but have to be enabled before a read or write access. This is independent whether you access the OTP register via the normal I2C pins or in application trimm mode via LINL and LINR. Please refer to the detailed register description to get more information on how the registers can be accessed.

To achieve a proper burning of the fuses, the negative supply has to be buffered by applying an external negative supply during burning. This voltage can also be applied to the LINL terminal. An internal switch is connecting LINL and VNEG during the fuse burning. LINR has to provide the clock for burning the fuses.

The below flow chart shows the principle steps of the OTP burning process. The application trimm mode can only be entered once. There is no possibility to stop the sequence, exit and re-enter the application trimm mode to make e.g. the verification in a second step. The OTP bring sequence has to be done as shown in the flow chart.

A more detailed description of the individual steps is available in an application note.

Figure 18. OTP Burning Process



8.8 2-Wire-Serial Control Interface

8.8.1 General

There is an I2C slave block implemented to have access to 64 byte of setting information.

The I2C address is: Adr_Group8 - audio processors

- 8Eh_write
- 8Fh_read

8.8.2 Protocol

Table 13. 2-Wire Serial Symbol Definition

Symbol	Definition	RW	Note
S	Start condition after stop	R	1 bit
Sr	Repeated start	R	1 bit
DW	Device address for write	R	1000 1110b (8Eh)
DR	Device address for read	R	1000 1111b (8Fh)
WA	Word address	R	8 bit
A	Acknowledge	W	1 bit
N	No Acknowledge	R	1 bit
reg_data	Register data/write	R	8 bit
data (n)	Register data/read	W	8 bit
P	Stop condition	R	1 bit
WA++	Increment word address internally	R	during acknowledge
	AS3500 AS3501 AS3502 (=slave) receives data		
	AS3500 AS3501 AS3502 (=slave) transmits data		

Figure 19. Byte Write

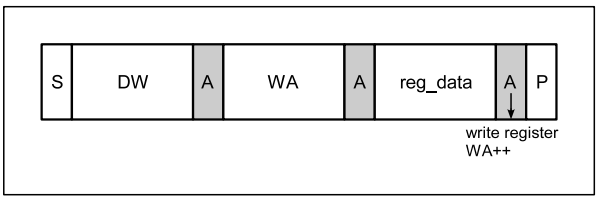
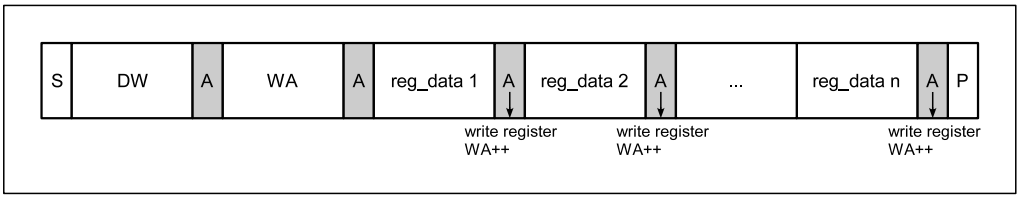


Figure 20. Page Write

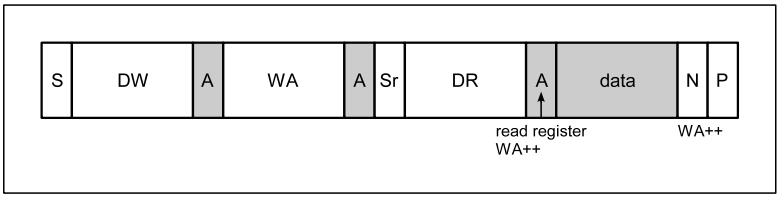


Byte Write and Page Write formats are used to write data to the slave.

The transmission begins with the START condition, which is generated by the master when the bus is in IDLE state (the bus is free). The device-write address is followed by the word address. After the word address any number of data bytes can be sent to the slave. The word address is incremented internally, in order to write subsequent data bytes on subsequent address locations.

For reading data from the slave device, the master has to change the transfer direction. This can be done either with a repeated START condition followed by the device-read address, or simply with a new transmission START followed by the device-read address, when the bus is in IDLE state. The device-read address is always followed by the 1st register byte transmitted from the slave. In Read Mode any number of subsequent register bytes can be read from the slave. The word address is incremented internally.

Figure 21. Random Read

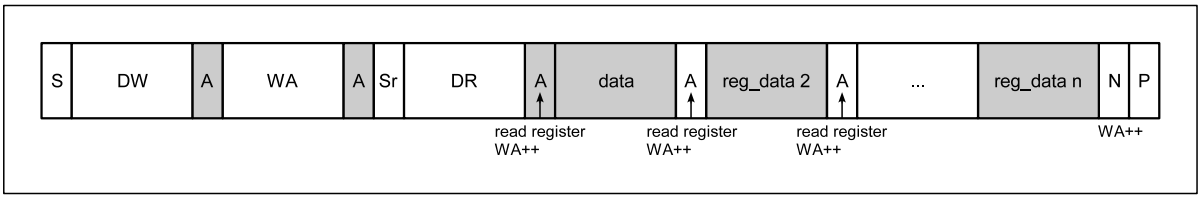


Random Read and Sequential Read are combined formats. The repeated START condition is used to change the direction after the data transfer from the master.

The word address transfer is initiated with a START condition issued by the master while the bus is idle. The START condition is followed by the device-write address and the word address.

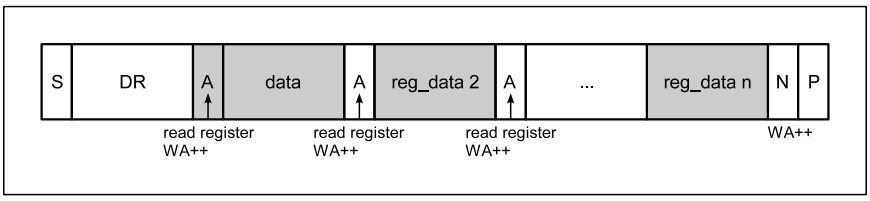
In order to change the data direction a repeated START condition is issued on the 1st SCL pulse after the acknowledge bit of the word address transfer. After the reception of the device-read address, the slave becomes the transmitter. In this state the slave transmits register data located by the previous received word address vector. The master responds to the data byte with a not-acknowledge, and issues a STOP condition on the bus.

Figure 22. Sequential Read



Sequential Read is the extended form of Random Read, as more than one register-data bytes are transferred subsequently. In difference to the Random Read, for a sequential read the transferred register-data bytes are responded by an acknowledge from the master. The number of data bytes transferred in one sequence is unlimited (consider the behavior of the word-address counter). To terminate the transmission the master has to send a not-acknowledge following the last data byte and generate the STOP condition subsequently.

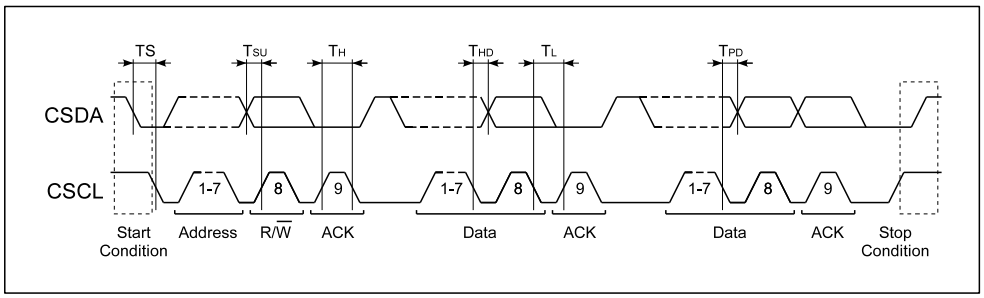
Figure 23. Current Address Read



To keep the access time as small as possible, this format allows a read access without the word address transfer in advance to the data transfer. The bus is idle and the master issues a START condition followed by the Device-Read address. Analogous to Random Read, a single byte transfer is terminated with a not-acknowledge after the 1st register byte. Analogous to Sequential Read an unlimited number of data bytes can be transferred, where the data bytes has to be responded with an acknowledge from the master. For termination of the transmission the master sends a not-acknowledge following the last data byte and a subsequent STOP condition.

8.8.3 Parameter

Figure 24. 2-Wire Serial Timing



DVDD =2.9V, T_{amb}=25ºC; unless otherwise specified

Table 14. 2-Wire Serial Parameter

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V_{CSL}	CSCL, CSDA Low Input Level	(max 30%DVDD)	0	-	0.87	V
V_{CSH}	CSCL, CSDA High Input Level	CSCL, CSDA (min 70%DVDD)	2.03	-	5.5	V
HYST	CSCL, CSDA Input Hysteresis		200	450	800	mV
V_{OL}	CSDA Low Output Level	at 3mA	-	-	0.4	V
Tsp	Spike insensitivity		50	100	-	ns
T_H	Clock high time	max. 400kHz clock speed	500			ns
T_L	Clock low time	max. 400kHz clock speed	500			ns
T_{SU}		CSDA has to change Tsetup before rising edge of CSCL	250	-	-	ns
T_{HD}		No hold time needed for CSDA relative to rising edge of CSCL	0	-	-	ns
TS		CSDA H hold time relative to CSDA edge for start/stop/rep_start	200	-	-	ns
T_{PD}		CSDA prop delay relative to lowgoing edge of CSCL		50		ns

9 Register Description

Table 15. I2C Register Overview

Addr	Name	b7	b6	b5	b4	b3	b2	b1	b0
Audio Registers									
00-07h	reserved								
08h	MIC_L	MIC_MODE 0: StereoSingleEnd 1: MonoDiff	MICL_VOL<6:0> Gain from MICL to QMICL or Mixer = -6dB...+41.6dB; 127 steps of 0.375dB						
09h	MIC_R	MIC_REG_ON 0: use reg 30h & 31h 1: use reg 08h & 09h	MICR_VOL<6:0> Gain from MICR to QMICR or Mixer = -6dB...+41.6dB; 127 steps of 0.375dB						
0Ah	LINE_IN	LIN_REG_ON 0: use reg 33h and VOL pin 1: use reg 0Ah	LIN_MODE 0: StereoSingleEnd 1: MonoDiff	LIN_VOL<5:0> 0: MUTE; 0x01..0x3F: Gain from LINR/L to QLINR/L or Mixer = -46.5dB...+0dB; 63 steps of 0.75dB					
0Bh	GP_OP_L	HP_MUX<1:0> 0: MIC; 1: OP1; 2: OP2; 3: open		OP2L<3:0> 0: OP2L inverting mode; 0x1..0xF: OP2L non inverting mode gain = 0...10.5dB; 15 steps of 0.75dB				OP2L_ON	OP1L_ON
0Ch	GP_OP_R	OP_REG_ON 0: use reg 34h 1: use reg 0Bh & 0Ch	HP_MODE 0: StereoSingleEnd 1: MonoDiff	OP2R<3:0> 0: OP2R inverting mode; 0x1..0xF: OP2R non inverting mode gain = 0...10.5dB; 15 steps of 0.75dB				OP2R_ON	OP1R_ON
0Dh-1Fh	reserved								
System Register									
20h	SYSTEM	Design_Version<3:0>				REG3F_ON	MONITOR_ON	CONT_PWRUP	PWR_HOLD
21h	PWR_SET	PWR_REG_ON 0: - 1: use reg 21h	ILED<1:0> 0: OFF; 1: 25%; 2: 50%; 3: 100%		HP_ON	MIC_ON	LIN_ON	MICS_CP_ON	MICS_ON
			LOW_BAT	PWRUP_COMPLETE					
22h-2Fh	reserved								

Table 15. I2C Register Overview

Addr	Name	b7	b6	b5	b4	b3	b2	b1	b0
OTP Register									
30h	ANC_L	TEST_BIT_1	MICL_VOL_OTP<6:0> Gain from MICL to QMICL or Mixer = -6dB...+41.6dB; 127 steps of 0.375dB						
31h	ANC_R	TEST_BIT_2	MICR_VOL_OTP<6:0> Gain from MICR to QMICR or Mixer = -6dB...+41.6dB; 127 steps of 0.375dB						
32h	MIC_MON	MON_MODE 0: fixed volume 1: adj. volume	MIC_MON_OTP<6:0> Gain from MICI/R to QMICL/R or Mixer = -6dB...+41.6dB; 0.375dB steps, if MON_MODE is set to 0 Gain from MICI/R to QMICL/R or Mixer = -6dB...+41.6dB; 0.375dB steps, adjustable by VOL pin if MON_MODE is set to 1						
33h	AUDIO_SET	VOL_PIN_OFF	VOL_PIN_ MODE 0: potentiometer 1: up/down button	LIN_MODE_ OTP 0: StereoSingleEnd 1: MonoDiff	MIC_MODE_ OTP 0: StereoSingleEnd 1: MonoDiff	HP_MODE_ OTP 0: StereoSingleEnd 1: MonoDiff	LIN_MON_ATTEN<2:0> 0: no attenuation; 1..6: LIN_VOL<6:0> shift by -6dB...-36dB 7: MUTE		
34h	GP_OP	HP_MUX_OTP<1:0> 0: MIC; 1: OP1; 2: OP2; 3: -		OP2_OTP<3:0> 0: OP2 inverting mode; 0x1..0xF: OP2 non inverting mode gain = 0...10.5dB; 15 steps of 0.75dB				OP2_ON_OTP	OP1_ON_OTP
35h	OTP_SYS	OTP_LOCK 0: write reg 30h.. 35h 1: lock reg 30h..35h	TEST_BIT_5	MON_HP_MUX<1:0> 0: MIC; 1: OP1; 2: OP2; 3: -		ILED_OTP<1:0> 0: OFF; 1: 25%; 2: 50%; 3: 100%		MICS_CP_OFF	I2C_MODE
36h-3Dh	reserved								
3Eh	CONFIG_1					EXTBURNCLK			
3Fh	CONFIG_2				BURNSW	TM_REG34-35	TM_REG30-33	OTP_MODE<1:0> 0: READ; 1: LOAD; 2: WRITE; 3: BURN	

Table 16. MIC_L Register

Name		Base		Default
MIC_L		**2-wire serial**		**00h**
Offset: 08h		**Left Microphone Input Register**		
		Configures the gain for the left microphone input and defines the microphone operation mode. This register is reset at POR.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	MIC_MODE	0	R/W	Selects the microphone input mode **0: single ended stereo mode** 1: mono differential mode
6:0	MICL_VOL<6:0>	000 0000	R/W	Volume settings for left microphone input, adjustable in 127 steps of 0.375dB **00 0000: MUTE** 00 0001: -5.625dB gain 00 0010: -5.25 dB gain .. 11 1110: 41.250dB gain 11 1111: 41.625 dB gain

Table 17. MIC_R Register

Name		Base		Default
MIC_R		**2-wire serial**		**00h**
Offset: 09h		**Right Microphone Input Register**		
		Configures the gain for the right microphone input and enables register 08h & 09h. This register is reset at POR.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	MIC_REG_ON	0	R/W	Defines which registers are used for the microphone settings. **0:settings of register 30h and 31h are used** 1: settings of register 08h and 09h are used
6:0	MICR_VOL<6:0>	000 0000	R/W	Volume settings for right microphone input, adjustable in 127 steps of 0.375dB **00 0000: MUTE** 00 0001: -5.625dB gain 00 0010: -5.25 dB gain .. 11 1110: 41.250dB gain 11 1111: 41.625 dB gain

Table 18. LINE_IN Register

Name		Base		Default
LINE_IN		**2-wire serial**		**00h**
Offset: 0Ah		**Line Input Register**		
		Configures the attenuation for the line input, defines the line input operation mode and enables register 0Ah. This register is reset at POR.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	LIN_REG_ON	0	R/W	Defines which source is used for the line input settings. **0: settings of register 33h and VOL pin are used** 1: register 0Ah is used
6	LIN_MODE	0	R/W	Selects the line input mode **0: single ended stereo mode** 1: mono differential mode
5:0	LIN_VOL<5:0>	00 0000	R/W	Volume settings for line input, adjustable in 63 steps of 0.75dB **00 0000: MUTE** 00 0001:-46.5dB gain 00 0010:-45.75dB dain .. 11 1110:-0.75dB gain 11 1111:.0 dB gain

Table 19. GP_OP_L Register

Name		Base		Default
GP_OP_L		**2-wire serial**		**00h**
Offset: 0Bh		**Left General Purpose Operational Amplifier Register**		
		Enables the left opamp stages, defines opamp 2 mode and gain and sets the HP input multiplexer. This register is reset at POR.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7:6	HP_MUX<1:0>	00	R/W	Multiplexes the analog audio signal to HP amp **00: MIC: selects QMICL/R output** 01: OP1: selects QOP1L/R outputs 10:OP2: selects QOP2L/R output 11: open: no signal mixed together with the line input signal
5:2	OP2L<3:0>	0000	R/W	Mode and volume settings for left OP2, adjustable in 15 steps of 0.75dB **0000: OP2L in inverting mode** 0001: 0 dB gain, OP2L in non inverting mode 0001: 0.75 dB gain, non inverting .., 1110: 9.75dB gain, non inverting 1111:.10.5 dB gain, non inverting
1	OP2L_ON	0	R/W	Enables left OP 2 **0: left OP2 is switched off** 1: left OP2 is enabled
0	OP1L_ON	0	R/W	Enables left OP 1 **0: left OP1 is switched off** 1: left OP1 is enabled

Table 20. GP_OP_R Register

Name		Base		Default
GP_OP_R		**2-wire serial**		**00h**
Offset: 0Ch		**Right General Purpose Operational Amplifier Register**		
		Enables the right opamp stages, defines opamp 2 mode and gain and sets the HP mode. This register is reset at POR.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	OP_REG_ON	0	R/W	Defines which register is used for the opamp and HP settings. **0: settings of register 33h and 34h are used** 1: register 0B and 0Ch are used
6	HP_MODE	0	R/W	Selects the line input mode **0: single ended stereo mode** 1: mono differential mode
5:2	OP2R<3:0>	0000	R/W	Mode and volume settings for right OP2, adjustable in 15 steps of 0.75dB **0000: OP2R in inverting mode** 0001: 0 dB gain, OP2R in non inverting mode 0001: 0.75 dB gain, non inverting .., 1110: 9.75dB gain, non inverting 1111:.10.5 dB gain, non inverting
1	OP2R_ON	0	R/W	Enables right OP 2 **0: right OP2 is switched off** 1: right OP2 is enabled
0	OP1R_ON	0	R/W	Enables right OP 1 **0: right OP1 is switched off** 1: right OP1 is enabled

Table 21. SYSTEM Register

Name		Base		Default
SYSTEM		**2-wire serial**		**31h**
Offset: 20h		**SYSTEM Register**		
		This register is reset at a POR.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7:4	Design_Version<3:0>	0011	R	AFE number to identify the design version 0011: for chip version 1v2
3	TESTREG_ON	0	R/W	0: normal operation 1: enables writing to test register 3Eh & 3Fh to configure the OTP and set the access mode.
2	MONITOR_ON	0	R/W	Enables the monitor mode **0: normal operation** 1: monitor mode enabled
1	CONT_PWRUP	0	R/W	Continues the automatic power-up sequence when using the I2C mode **0: chip stops the power-up sequence after the supplies are stable, switching on individual blocks has to be done via I2C commands** 1: automatic power-up sequence is continued
0	PWR_HOLD	1	R/W	0: power up hold is cleared and AFE will power down **1: is automatically set to on after power on**

Table 22. PWR_SET Register

Name		Base		Default
PWR_SET		**2-wire serial**		**0x11 1111b (stand alone mode) 0x00 0000b (I2C mode)**
Offset: 21h		**Power Setting Register**		
		Please be aware that writing to this register will enable/disable the corresponding blocks, while reading gets the actual status. It is not possible to read back e.g ILED settings. This register is reset at POR.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	PWR_REG_ON	0	R/W	Defines which register is used for the power settings. **0: all blocks stay on as defined in the start-up sequence** 1: register 21h is used
6:5	ILED<1:0>	00	W	Sets the current sunk into ILED **00: current sink switched OFF** 01: 25% 10: 50% 11: 100%
6	LOW_BAT	x	R	VBAT supervisor status **0: VBAT is above brown out level** 1: BVDD has reached brown out level
5	PWRUP_COMPLETE	x	R	Power-Up sequencer status **0: power-up sequence incomplete** 1: power-up sequence completed
4	HP_ON	0	W	**0: switches HP stage off** 1: switches HP stage on
		x	R	**0: HP stage not powered** 1: normal operation
3	MIC_ON	0	W	**0: switches microphone stage off** 1: switches microphone stage on
		x	R	**0: microphone stage not powered** 1: normal operation
2	LIN_ON	0	W	**0: switches line input stage off** 1: switches line input stage on
		x	R	**0: line input stage not powered** 1: normal operation
1	MICS_CP_ON	0	W	**0: switches microphone supply charge pump off** 1: switches microphone supply charge pump on
		x	R	**0: microphone supply charge pump not powered** 1: normal operation
0	MICS_ON	0	W	**0: switches microphone supply off** 1: switches microphone supply on
		x	R	**0: microphone supply not enabled** 1: normal operation

Table 23. ANC_L Register

Name		Base		Default
ANC_L		**2-wire serial**		**80h (OTP)**
Offset: 30h		**Left OTP Microphone Input Register**		
		Configures the gain for the left microphone input. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	TEST_BIT1	1	R	for testing purpose only
6:0	MICL_VOL_OTP <6:0>	000 0000	R/W	Volume settings for left microphone input, adjustable in 127 steps of 0.375dB **00 0000: MUTE** 00 0001: -5.625dB gain 00 0010: -5.25 dB gain .. 11 1110: 41.250dB gain 11 1111: 41.625 dB gain

Table 24. ANC_R Register

Name		Base		Default
ANC_R		**2-wire serial**		**80h (OTP)**
Offset: 31h		**Right OTP Microphone Input Register**		
		Configures the gain for the left microphone input. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	TEST_BIT2	1	R	for testing purpose only
6:0	MICR_VOL_OTP <6:0>	000 0000	R/W	Volume settings for right microphone input, adjustable in 127 steps of 0.375dB **00 0000: MUTE** 00 0001: -5.625dB gain 00 0010: -5.25 dB gain .. 11 1110: 41.250dB gain 11 1111: 41.625 dB gain

Table 25. MIC_MON Register

Name		Base		Default
MIC_MON		**2-wire serial**		**00h (OTP)**
Offset: 32h		**OPT Microphone Monitor Mode Register**		
		Configures the gain for the microphone input in monitor mode. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	MON_MODE	0	R/W	**0: monitor mode is working with fixed microphone gain** 1: monitor mode uses adjustable gain via the VOL pin
6:0	MIC_MON_OTP <6:0>	000 0000	R/W	Volume settings for microphone input during monitor mode, adjustable in 127 steps of 0.375dB. If MON_MODE bit is set to 1 the gain can be further adjusted via the VOL pin. **00 0000: MUTE** 00 0001: -5.625dB gain 00 0010: -5.25 dB gain .. 11 1110: 41.250dB gain 11 1111: 41.625 dB gain

Table 26. AUDIO_SET Register

Name		Base		Default
AUDIO_SET		**2-wire serial**		**00h (OTP)**
Offset: 33h		**OPT Audio Setting Register**		
		Configures the audio settings. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	VOL_PIN_OFF	0	R/W	**0: VOL pin is enabled** 1: line in volume settings can only be done via I2C. VOL_PIN_MODE has to be set to 1 in this mode.
6	VOL_PIN_MODE	0	R/W	**0: VOL pin is in potentiometer mode** 1: VOL pin is in up/down button mode
5	LIN_MODE_OTP	0	R/W	**0: line input stage opeating in single ended mode** 1: line input operating in mono balanced
4	MIC_MODE_OTP	0	R/W	**0: microphone input stage opeating in single ended mode** 1: normal operating in mono balanced
3	HP_MODE_OTP	0	R/W	**0: headphone stage opeating in single ended mode** 1: normal operating in mono balanced
2:0	LIN_MON_ATTEN <6:0>	000	R/W	Volume settings for line input during monitor mode, adjustable in 7 steps of 6dB and mute. **000: 0dB gain** 001: -6dB gain .. 110: -36dB gain 111: MUTE

Table 27. GP_OP Register

Name		Base		Default
GP_OP		**2-wire serial**		**00h (OTP)**
Offset: 34h		**OTP General Purpose Operational Amplifier Register**		
		Enables the opamp stages, defines opamp 2 mode and gain and sets the HP input multiplexer. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7:6	HP_MUX_OTP<1:0>	00	R/W	Multiplexes the analog audio signal to HP amp **00: MIC: selects QMICL/R output** 01:OP1: selects QOP1L/R outputs 10:OP2: selects QOP2L/R output 11: open: no signal mixed together with the line input signal
5:2	OP2_OTP<3:0>	0000	R/W	Mode and volume settings for OP2, adjustable in 15 steps of 0.75dB **0000: OP2L in inverting mode** 0001: 0 dB gain, OP2L in non inverting mode 0001: 0.75 dB gain, non inverting .., 1110: 9.75dB gain, non inverting 1111:.10.5 dB gain, non inverting
1	OP2_ON	0	R/W	**0: OP2 is switched off** 1: left OP2 is enabled
0	OPL_ON	0	R/W	**0: OP1 is switched off** 1: OP1 is enabled

Table 28. OTP_SYS Register

Name		Base		Default
OTP_SYS		**2-wire serial**		**40h (OTP)**
Offset: 35h		**OTP System Settings Register**		
		Defines several system settings for OTP operation. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7	OTP_LOCK	0	R/W	**0: additional bits can be fused inside the OTP** 1: OTP fusing gets locked, no more changes can be done
6	TEST_BIT5	1	R	for testing purpose only
5:4	MON_HP_MUX <1:0>	00	R/W	Multiplexes the analog audio signal to HP amp in monitor mode **00: MIC: selects QMICL/R output** 01: OP1: selects QOP1L/R outputs 10:OP2: selects QOP2L/R output 11: open: no signal mixed together with the line input signal
3:2	ILED_OTP<1:0>	00	W	Sets the current sunk into ILED **00: current sink switched OFF** 01: 25% 10: 50% 11: 100%

Table 28. OTP_SYS Register

Name		Base		Default
OTP_SYS		**2-wire serial**		**40h (OTP)**
Offset: 35h		**OTP System Settings Register**		
		Defines several system settings for OTP operation. This is a special register, writing needs to be enabled by writing 10b to Reg 3Fh first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
1	MICS_CP_OFF	0	R/W	**0: MICS charge pump is enabled** 1: MICS charge pump is switched off
0	I2C	0	R/W	**0: I2C and stand alone mode start-up possible** 1: chip starts-up in I2C mode only

Table 29. CONFIG_1 Register

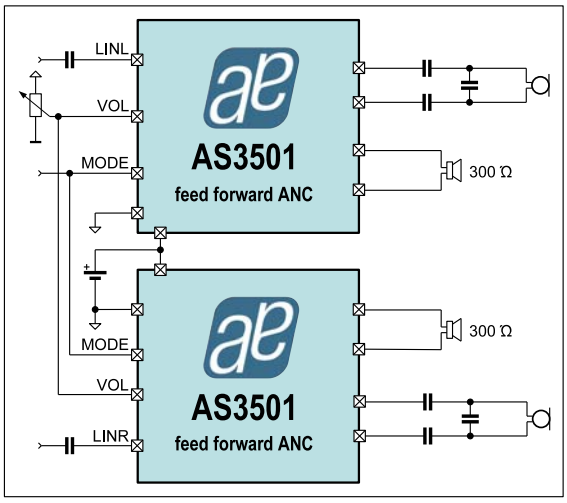
Name		Base		Default
CONFIG_1		**2-wire serial**		**00h**
Offset: 3Eh		**OTP Configuration Register**		
		Controls the clock configuration. This is a special register, writing needs to be enabled by writing 9h to Reg 20h first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7:4	-	0000	n/a	
3	EXTBURNCLK	0	n/a	**0: ext. clock for OTP burning disabled** 1: ext. clock for OTP burning enabled
2:0	-	000	n/a	

Table 30. CONFIG_2 Register

Name		Base		Default
CONFIG_2		**2-wire serial**		**00h**
Offset: 3Fh		**OTP Access Configuration Register**		
		Controls the OTP access. This is a special register, writing needs to be enabled by writing 9h to Reg 20h first. This register is reset at POR and gets loaded with the OTP fuse contents.		
Bit	**Bit Name**	**Default**	**Access**	**Bit Description**
7:5	-	000	n/a	
4	BURNSW	0	n/a	**0: BURN switch from LINL to VNEG is disabled** 1: BURN switch from LINL to VNEG is enabled
3	TM_REG34-35	0	n/a	**0: test mode for Register 34h-35h disabled** 1: test mode for Register 34h-35h enabled
2	TM_REG30-33	0	n/a	**0: test mode for Register 30h-33h disabled** 1: test mode for Register 30h-33h enabled
1:0	OTP_MODE<1:0>	00	R/W	Controls the OTP access **00: READ** 01: LOAD 10: WRITE 11: BURN

10 Application Information

Figure 25. AS3501 High Performance Application in Bridged Mode for high impedance headsets



For high impedance headphones two AS3501 can be used in a bridged mode each one driving one side of the headphone load as differential output to get 24mW output power per channel. Also the microphone inputs can be used in differential mode to reduce the noise level.

Figure 26. AS3502 on Music Player with ANC

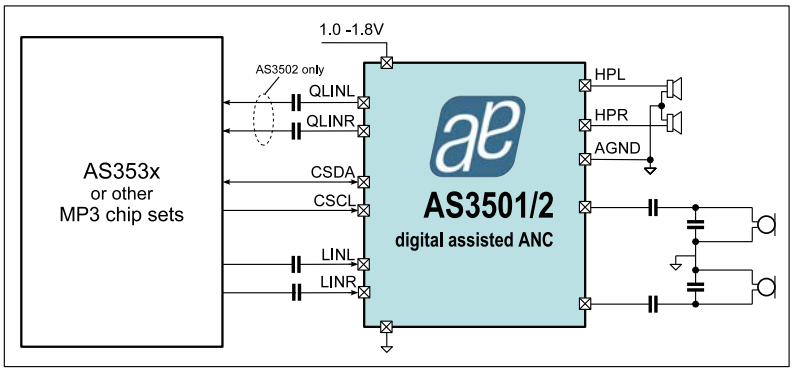


Figure 27. AS3501 feed-forward application example

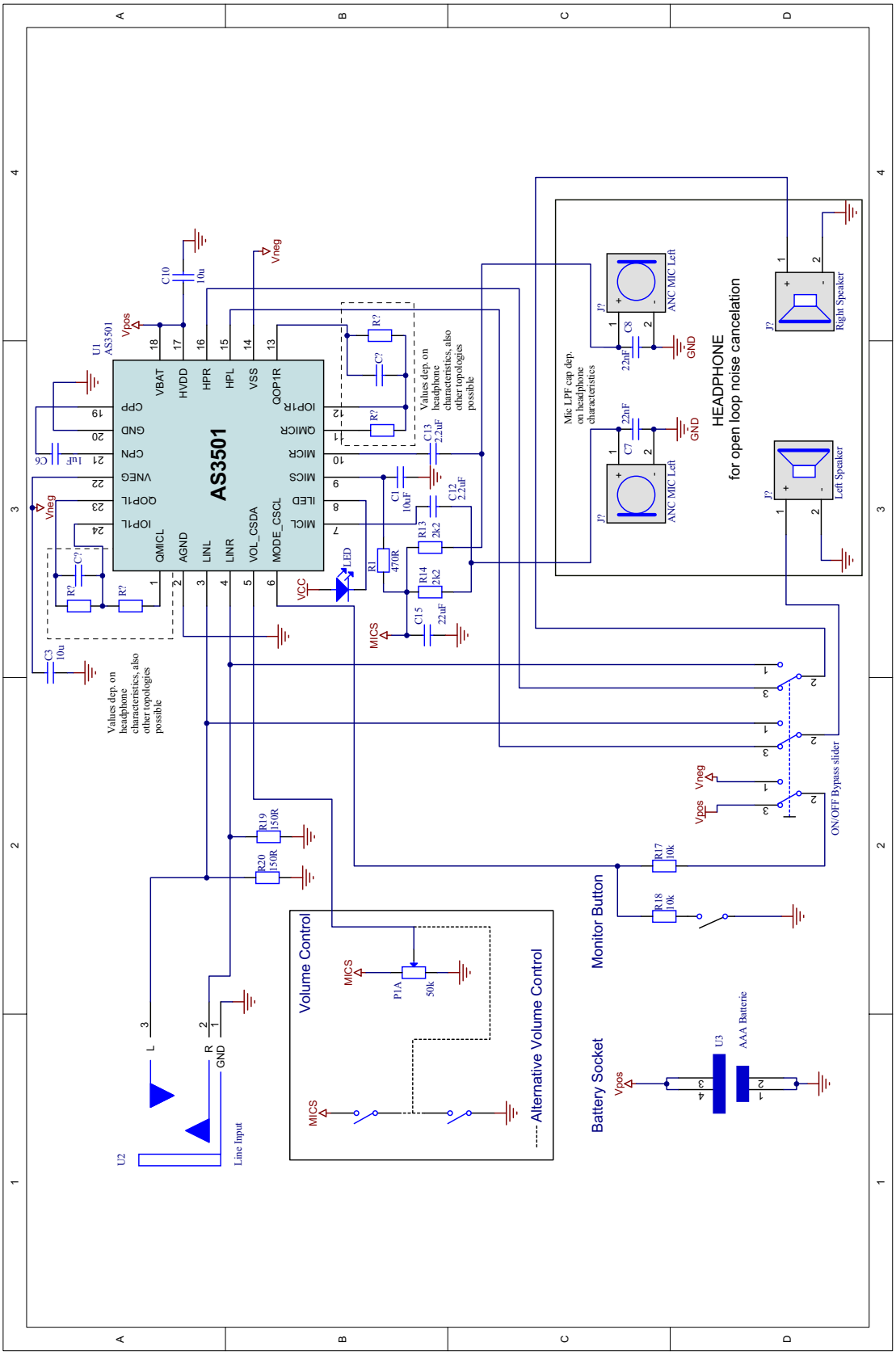


Figure 28. AS3502 feed-back application example

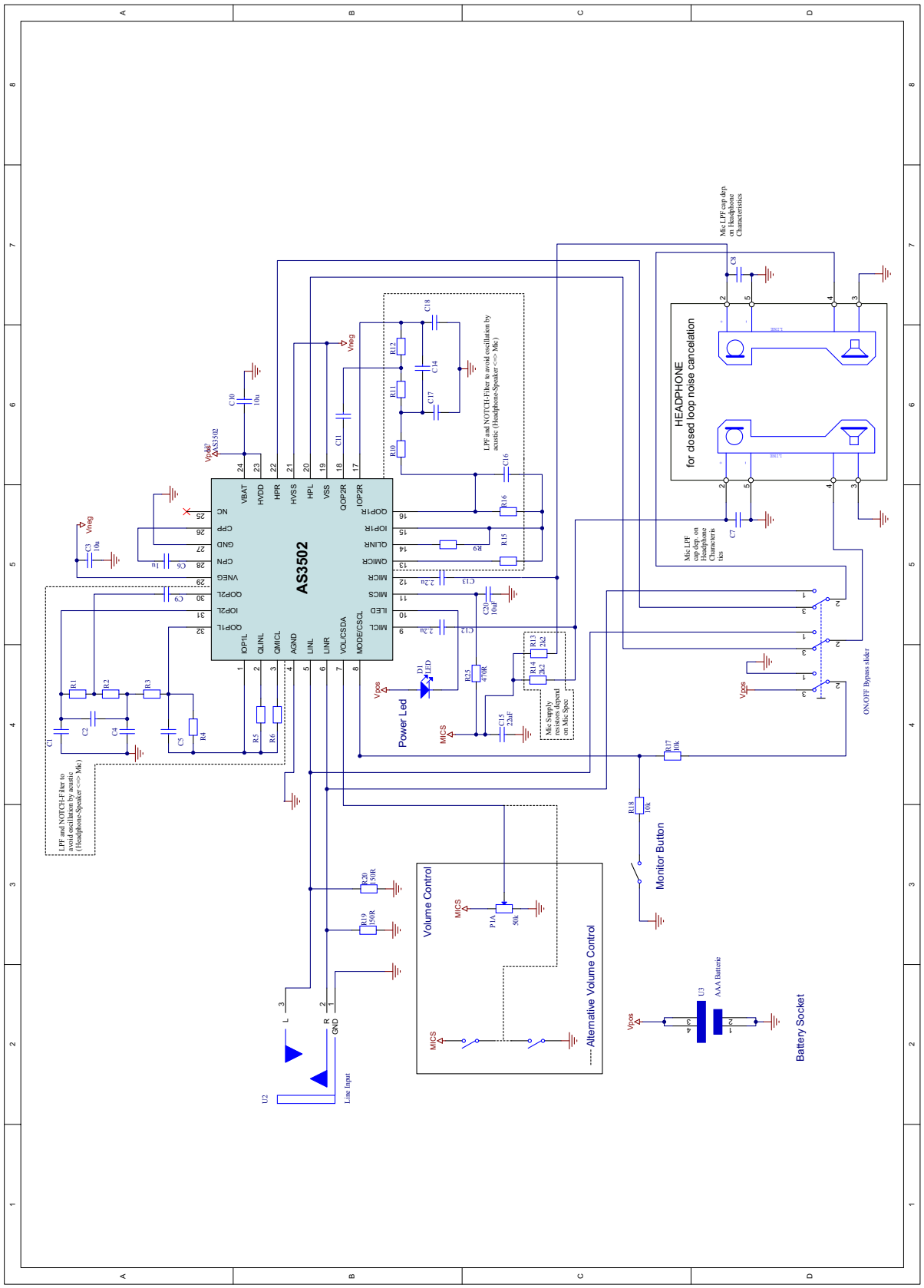


Figure 29. AS3501 Li-Ion battery bridged mode differential feed forward application example

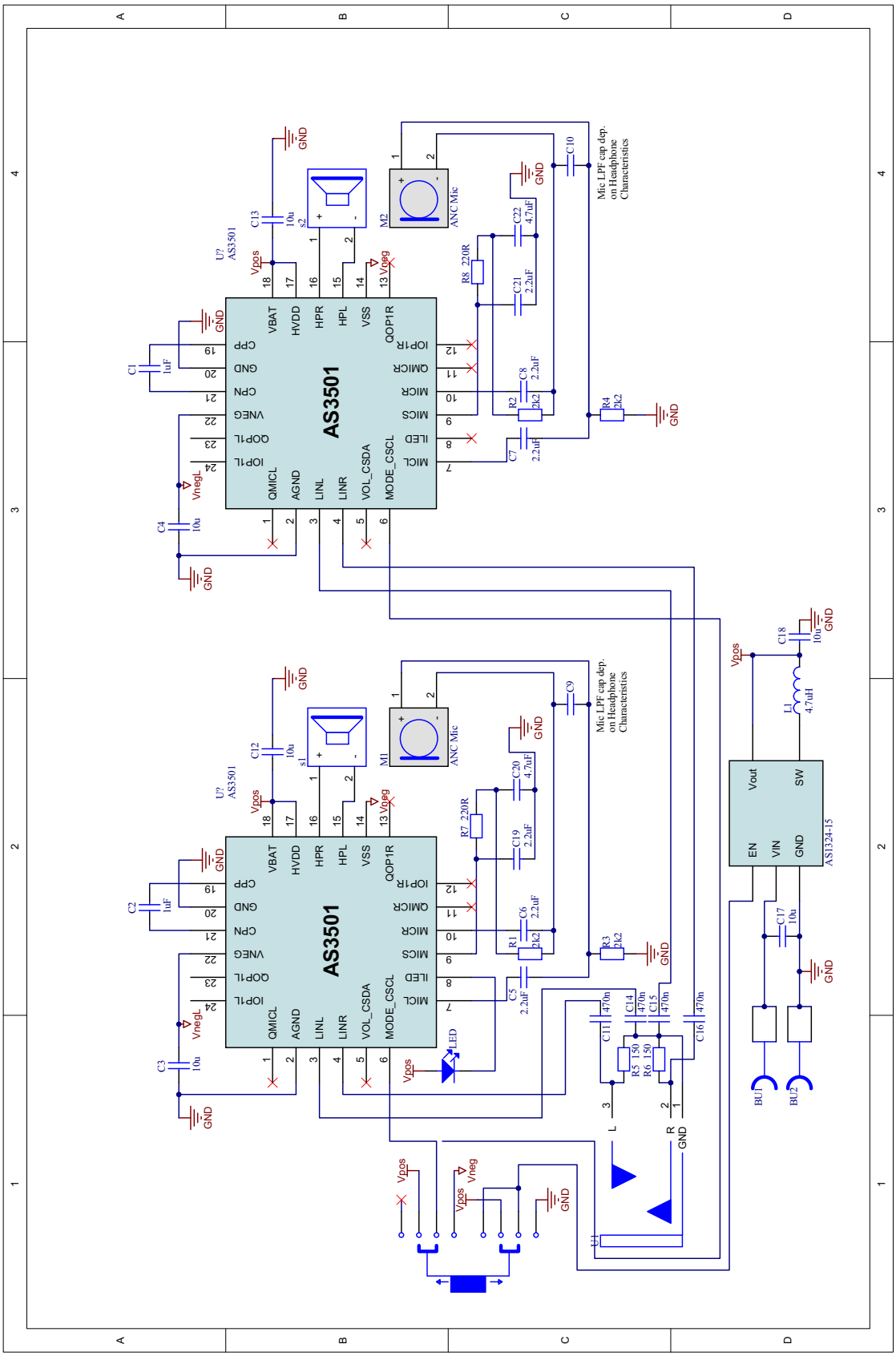
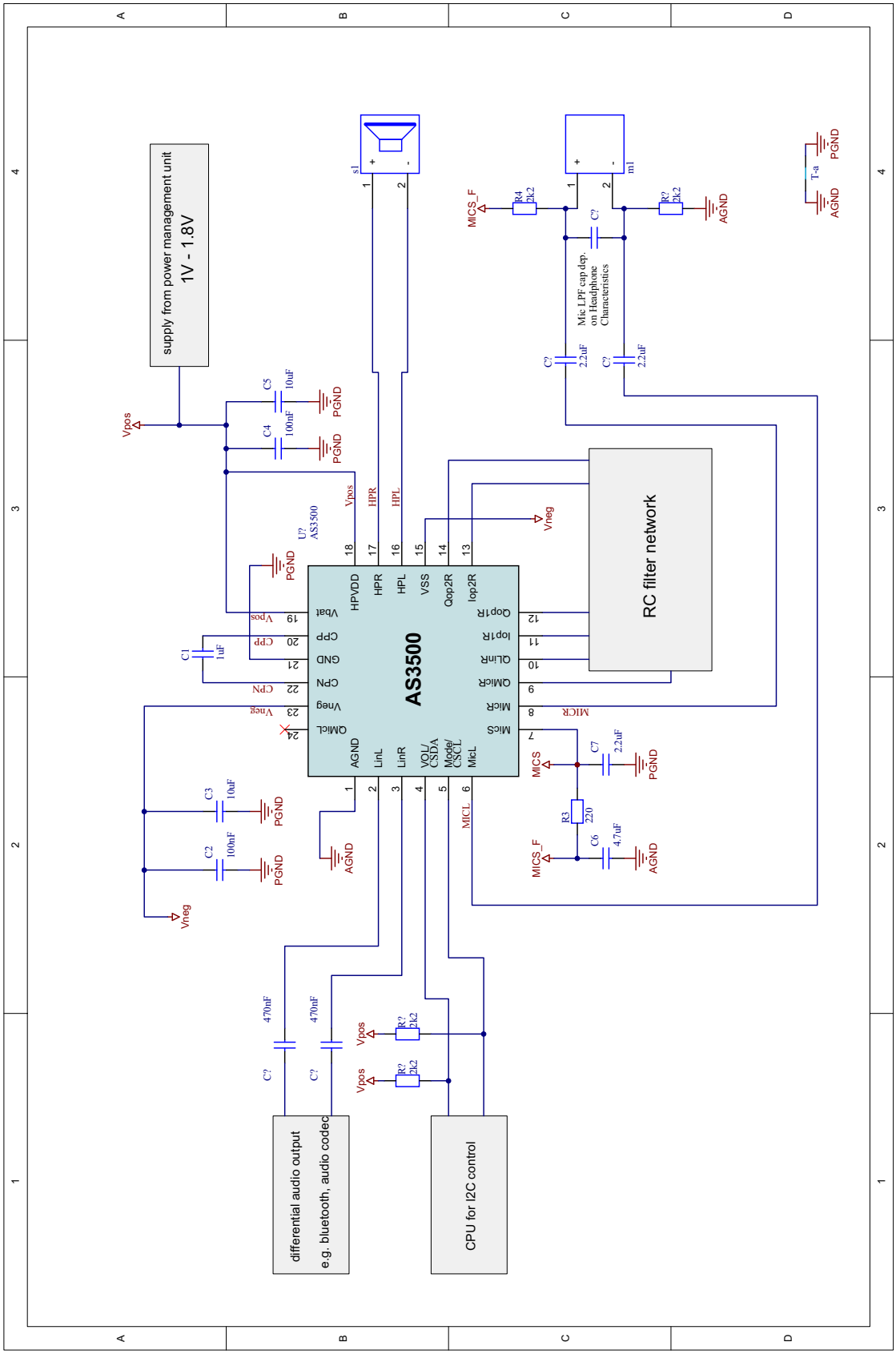


Figure 30. AS3500 feed - forward application example



11 Package Drawings and Markings

Figure 31. QFN Marking

Table 31. Package Code AYWWZZZ

A	Y	WW	ZZZ
A ... for Pb-free	year	working week assembly / packaging	free choice

Figure 32. AS3500, AS3501; QFN24 0.5mm pitch

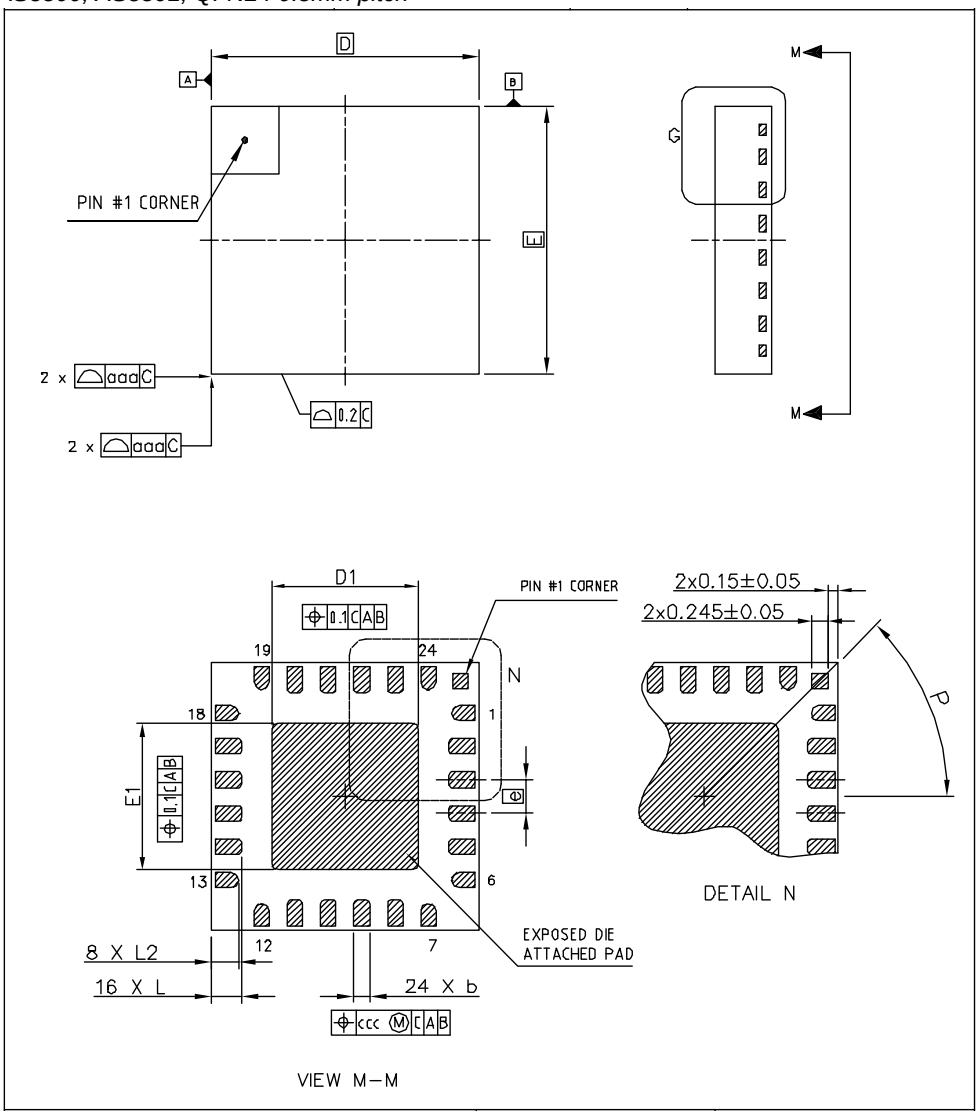
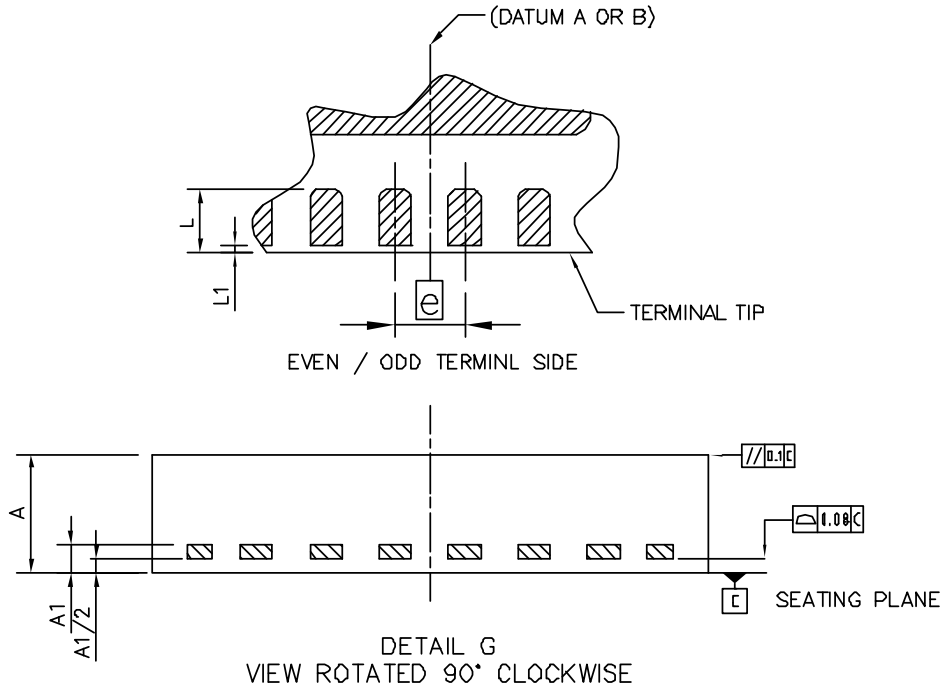


Figure 33. AS3500, AS3501; QFN24 0.5mm pitch details



DIM	MIN	NOM	MAX
A	0.75	0.85	0.95
A1	0.19		0.21
b	0.18	0.23	0.28
D		4.0 BSC	
E		4.0 BSC	
e		0.50 BSC	
D1	2.10	2.20	2.30
E1	2.10	2.20	2.30
L	0.40	0.50	0.60
L1			0.10
L2	0.30	0.40	0.50
P		45° REF	
aaa		0.10	
ccc		0.10	

NOTES

1.0 DIMENSIONING & TOLERANCEING CONFIRM TO ASME Y14.5M-1994.

2.0 ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

3.0 DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25mm AND 0.30mm FROM TERMINAL TIP. DIMENSION L1 REPRESENTS TERMINAL FULL BACK FROM PACKAGE EDGE UP TO 0.1mm IS ACCEPTABLE.

4.0 COPLANARITY APPLIES TO THE EXPOSED HEAT SLUG AS WELL AS THE TERMINAL.

5.0 RADIUS ON TERMINAL IS OPTIONAL.

UNIT	DIMENSION AND TOLERANCE	REFERENCE DOCUMENT
Millimeter(mm)	ASME Y14.5M	JEDEC MO-220

Figure 34. AS3502; QFN32 0.5mm pitch

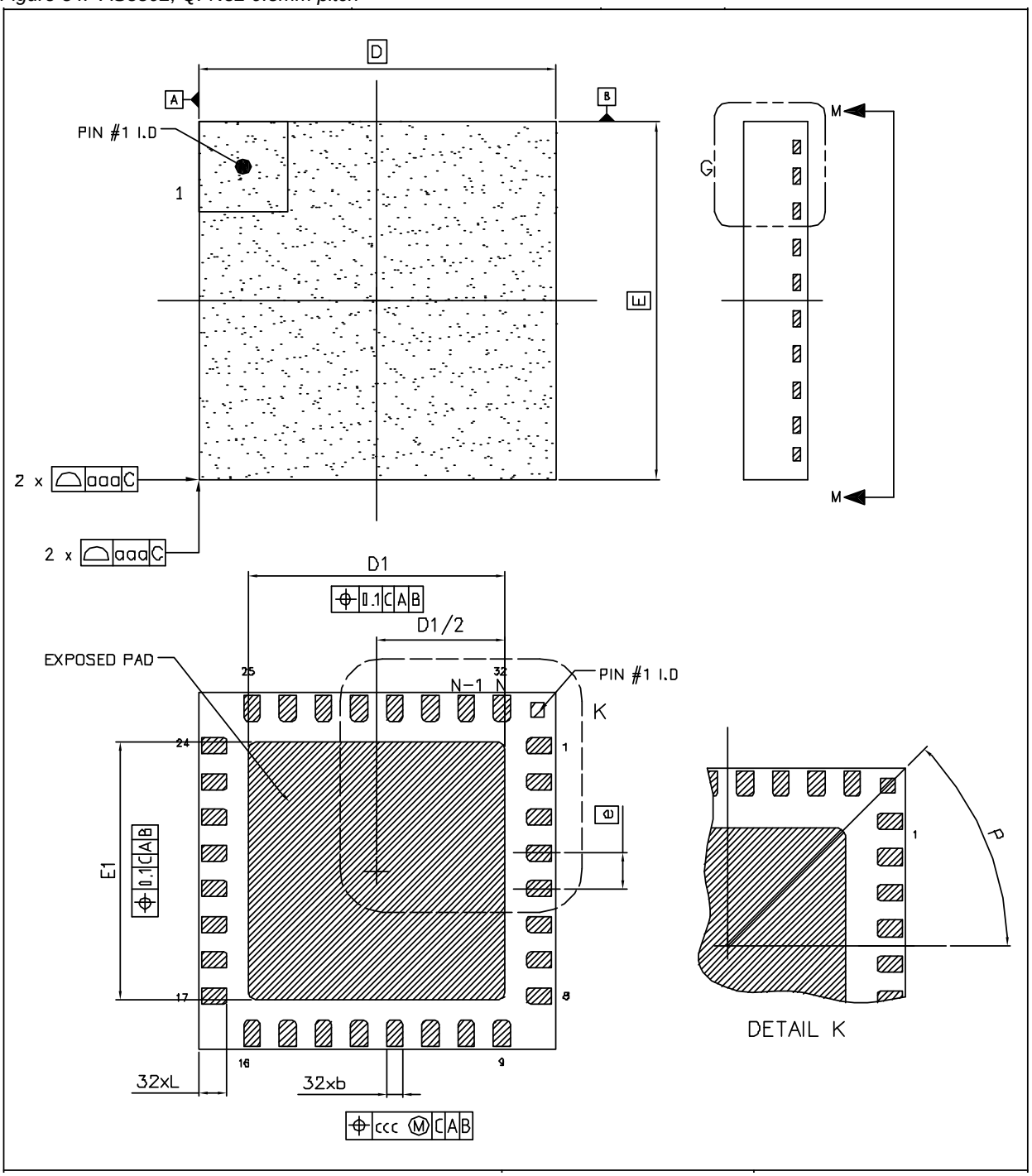
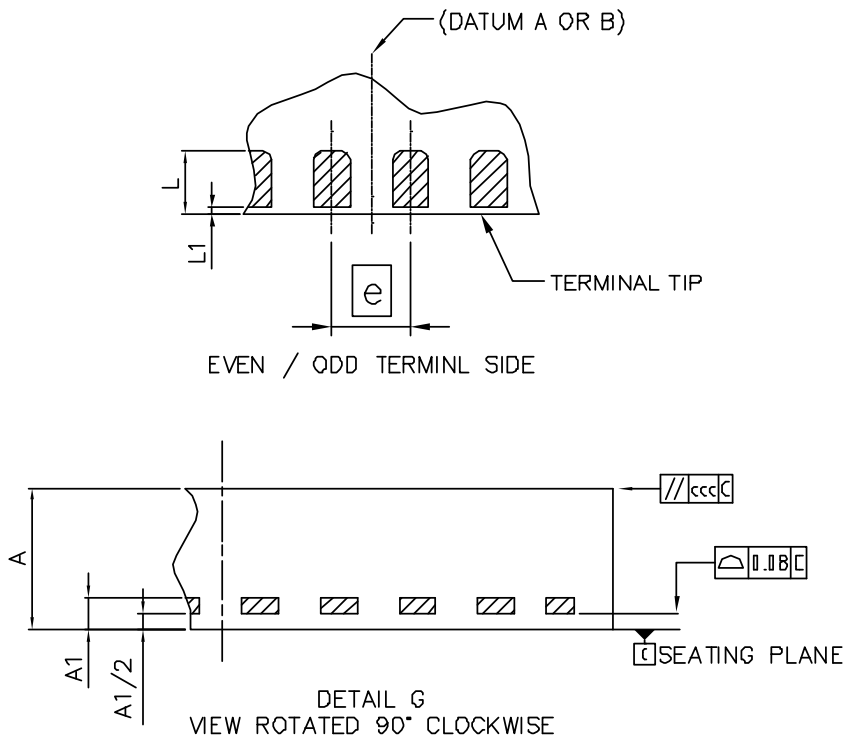


Figure 35. AS3502; QFN32 0.5mm pitch details



DIM	MIN	NOM	MAX
A	0.80		1.00
A1		0.203 REF	
b	0.18	0.23	0.30
D		5.00 BSC	
E		5.00 BSC	
D1	3.50	3.60	3.70
E1	3.50	3.60	3.70
e		0.50 BSC	
L	0.30	0.40	0.50
L1			0.10
P		45° BSC	
aaa		0.15	
ccc		0.10	

NOTES

1.0 DIMENSIONING & TOLERANCEING CONFIRM TO ASME Y14.5M-1994.

2.0 ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

3.0 DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25mm AND 0.30mm FROM TERMINAL TIP. DIMENSION L1 REPRESENTS TERMINAL FULL BACK FROM PACKAGE EDGE UP TO 0.1mm IS ACCEPTABLE.

4.0 COPLANARITY APPLIES TO THE EXPOSED HEAT SLUG AS WELL AS THE TERMINAL.

5.0 RADIUS ON TERMINAL IS OPTIONAL.

UNIT	DIMENSION AND TOLERANCE	REFERENCE DOCUMENT
Millimeter(mm)	ASME Y14.5M	JEDEC MO-220

12 Ordering Information

Table 32. Ordering Information

Model	Description	Delivery Form	Package
AS3500-EQFP	Low Power Ambient Noise-Cancelling Speaker Driver	Tape & Reel dry pack	QFN 24 [4.0x4.0x0.85mm] 0.5mm pitch
AS3501-EQFP	Low Power Ambient Noise-Cancelling Speaker Driver	Tape & Reel dry pack	QFN 24 [4.0x4.0x0.85mm] 0.5mm pitch
AS3502-EQFP	Low Power Ambient Noise-Cancelling Speaker Driver	Tape & Reel dry pack	QFN 32 [5.0x5.0x0.85mm] 0.5mm pitch

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Contact Information

Headquarters
austriamicrosystems AG
A-8141 Schloss Premstaetten, Austria

Tel: +43 (0) 3136 500 0
Fax: +43 (0) 3136 525 01

For Sales Offices, Distributors and Representatives, please visit:

http://www.austriamicrosystems.com/contact